

1.85C471 OVERVIEW

1.1 Introduction

The SiS85C471 single chip controller supports Intel's 80486DX2/DX/SX/SL Enhanced, P24D/P24T/P24C CPU, Cyrix's Cx486S2 (M6/M7) CPU and AMD's Am486DXL/DXL2 CPU.

The SiS85C471 is a high performance, 100% PC/AT compatible single chip controller, designed for cached/non-cached P24D/P24T/P24C, M6/M7 or 486 PC systems. The high integration of the powerful cache controller, the DRAM controller, the CPU interfaces, the bus controller, the data buffers and the peripheral controllers provides an easy and economical solution for compact board manufacturing.

In addition to supporting burst reads for the cache line fills of the CPU, the SiS85C471 is capable of accepting burst write data of the CPU's internal cache dirty line(s) during CPU write-back cycles. The support of the CPU burst write cycle is optional through the control of the Configuration Registers. The SiS85C471 supports the cache size up to 1 MB and the DRAM size up to 128 MB.

The SiS85C471 has a built-in cache controller which supports direct mapped writethrough/write-back cache. The programmable AT-bus clock supports are compatible with AT-bus timing requirements for different PC systems.

In addition, the local bus interfaces, the integration of the DMA Controllers, Interrupt Controllers and Timers/Counters are designed to be a higher performance, more compact, and more cost-effective product for a P24D/P24T/P24C, 486SX/DX/DX2/SL-Enhanced, Am486DXL/DXL2, or a Cx486S2 (M6/M7) PC/AT system.

The SiS85C471 provides power saving features to allow a system, through the control of BIOS, to reduce the CPU clock frequency from 50MHz down to 0 MHz(STOP CLOCK) when the system is idle.

To support the SL-Enchanced 486, M6/M7, P24D/P24T/P24C's Am486DXL/DXL2 STPCLK/SMI features, the SiS85C471 also implements the corresponding logics to support STPCLK /SMI for power saving.

The SiS85C471 supports the VL-Bus applications including (1) CPU accesses VL-Bus targets, (2) VL-Bus master mode, and (3) DMA or ISA master accesses VL-Bus targets.

The SiS85C471 provides flexible ways in configuring the system depending on whether cache or VESA local bus masters are supported. The different configurations require different numbers of external components.



1.2 Features

- Fully IBM PC/AT Compatible. 80486DX2/DX/SX/SL Enhanced, P24D/P24T/P24C, M6/M7 and Am486DXL/Am486DXL2 Single Chip Controller
- Supports L1 Cache Write back CPU (P24T/P24D/M6/M7) systems
- Direct Mapped Cache Controller
 - Write-Back or Write-Through Schemes
 - Bank Interleave or Non-Interleave Cache
 - 0/1 Wait State Cache Write Hit
 - Flexible Cache Size : 32/64/128/256/512KB or 1MB
 - 7 bits or 8 bits TAG addresses
 - Flexible 2-1-1-1, 3-1-1-1, 2-2-2-2 and 3-2-2-2 Burst Read/Write Timing
- Fast Page Burst Mode DRAM Controller
 - 4 Banks up to 128MB of DRAMs
 - 256K/512K/1M/2M/4M/16MxN DRAM Type
 - Programmable DRAM Speed
 - Double-sided SIMMs
- Two Programmable Non-Cacheable Regions (64KB-4MB area)
- CAS before RAS Transparent DRAM Refresh
- BIOS/Video ROM Cacheable
- Shadow RAM in Increments of 32KB - Option to Disable Cache in Shadow RAM Area
- 256K Memory Relocation
- 8042 Emulation of Fast A20GATE and CPU Reset
- Supports Port 92h
- Hardware/Software De-Turbo Switch
- Supports Two VL-Bus Master
- Supports Flash Memory
- Supports Double/Single frequency input
- CPU Operating frequency 0-100 MHz
- Supports Power Management Mode
- Supports the SMM and the SMI
- CPU Stop Clock Function
- Four Power Saving States
- Long and Short System Timers
- Supports the APM control
- Supports Break Switch control
- Power Saving also on non-SMI CPU
- More System Event Monitoring and the Power Saving Control
- AT Bus State Machine and Controller
- Synchronous/Asynchronous AT Bus Clock
- Programmable AT Bus Speed
 - 1/2,1/3,1/4,1/5,1/6,1/8,1/10 of Input Clock or 7.159MHz
- Programmable Wait State Generation
 - 1 or 2 Wait States for 16-Bit Transfers
 - 4 or 5 Wait States for 8-Bit Transfers
- Programmable I/O Recovery Time
- Programmable driving current for the DRAM and the ISA bus signals
- 32-Bit Data Buffer Between CPU and AT System
- Data Conversion and Swapping Logic for 32-/16-/8-Bit Transfers During CPU and DMA Cycles



- Data Latches for AT Read Cycles
- Parity Generation and Detection Logic
- Port B Register and NMI Logic
- Integrated Peripheral Controllers
 - 8259A x2 / 8237x2 / 8254 / 74LS612
- 387/487SX and Weitek 3167/4167 Coprocessors Interface
- 208-Pin PQFP
- 0.8µm Low Power CMOS Technology



1.3 Block Diagram

VESA TARGETs without CACHE application



VESA TARGETs with CACHE application



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Two VESA MASTERs without CACHE application



Two VESA MASTERs With CACHE application



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2 FUNCTIONAL DESCRIPTION

2.1 Cache Controller

2.1.1 Direct Mapped Cache

In a write-through cache system, data are written to the main memory while or immediately after they are written into the cache. So the main memory always contains valid data.

Cache is a good way in de-coupling the fast processor from the slow main memory and gets the best performance for the processor. Direct-mapped cache is the most straight-forward, flexible, easy-to-implement and cost-effective cache structure. A 2/4-way set-associative cache has better performance than the direct-mapped cache, but the performance difference is negligible when the cache size is large enough (e.g. 64KB). The SiS85C471 supports both write through and write back, for both the first level and the second level caches. To maintain the caches coherency, the SiS85C471 allows the CPU or the VL-Master to write back the entire dirty line to either the second level caches or the main memory via a completed burst write transfer. The SiS85C471 also provides a fast 8-bit/7-bit tag comparator and all the control logics for the second level cache of the 80486 processor. To implement a secondary cache, users only need to add SRAMs for the tag and the data memory onto the system. The maximum configurable cache size through the register is 1 MB.

2.1.2 Write-Back vs. Write-Through

When the contents of the cache data are modified by the processor, the main memory has to be updated. Failing to do so will raise an inconsistency problem when the stale data in the main memory are accessed. There are two approaches to update the main memory. The first is the write-through method and the second is the write-back (also called "copy-back") method. In a write-back cache system, there is a dirty bit for each cache data line. When a write hit occurs in a cache line, the corresponding "alter" bit will be set. The data are written to the main memory when the line is replaced by a cache line fill. When a cache line fill occurs, the cache controller checks the corresponding "alter" bit. If the "alter" bit is set, the cache data will then be written to the main memory before the cache line fill starts.

A write-back cache offers higher performance than a write-through cache if writes to the main memory are much slower than to the cache. A write-back cache is also favored when data are written to a memory location several times in the cache before they are written into the main memory. The performance advantage of the write-back cache over write-through cache is software dependent.

The SiS85C471 can be configured to support a write-back or write-through cache. The TAG address field of the SiS85C471 for the caches can either be programmed in 7-bit or 8-bit wide. Besides tag and data RAMs, a write-back cache may need a SRAM for the dirty bits if the TAG RAM and the ALTER RAM can not be shared in one SRAM. So, a write-back cache may have better performance, but costs more than a write-through cache. The cost/effectiveness is justified by application requirements.

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2.1.3 80486 Burst Cache Line Fill

The internal cache of the 80486 has a 16-byte line size. When a read miss occurs in the internal cache, the 80486 initiates off-chip memory read cycles to update the current cache line. The 80486 reads the 16-byte block (4 doublewords). To increase the bus throughput, the 80486 provides a burst mode transfer. Four doublewords can be read sequentially in 5 processor clocks (2-1-1).

The second level cache provided by the SiS85C471 also has a 16-byte line size. It supports the 80486 burst read cycles to do the fastest cache line fill. When the 80486 internal and external caches encounter a read miss, they are both updated with the data line read from the DRAMs simultaneously.

In addition to supporting burst reads for the cache line fills of the CPU, the SiS85C471 is capable of accepting burst write data of the CPU's internal cache dirty line(s) during CPU write back cycles. The CPU burst write support is optional by programming the Configuration Registers. The SiS85C471 supports the cache size up to 1MB and the DRAM size up to 128MB.

2.1.4 Cache Update Policy

For CPU cycles, the contents of the cache memory are updated when either the cache read miss or write hit occurs. Tag and data RAMs are both updated in the cache read miss cycles. In the cache write hit cycles, the SiS85C471 updates only the data RAM. In the cache write miss cycles, the CPU writes data into the main memory (DRAMs), while the cache memory remains unchanged. The "alter" bit of the data line in a write-back cache is reset in a cache update (read miss) cycle and set in a write hit cycle.

When the cache is disabled, all the CPU reads from the memory are treated as cache read misses, so both tag and data RAMs are updated. This feature is used to initialize the cache memory before it is enabled.

In DMA/ISA master cycles, the cache data RAMs are written when a write hit occurs to assure the cache coherency. Cache memory is not accessed in DMA/ISA master write miss or read cycles for the write-through cache. For the write-back cache, DMA/ISA master read hit cycles are conducted to the cache, not to the DRAMs.

2.1.5 Cache Size Options

Cache Size	Tag RAM	Alter RAM	Data RAM	Cacheable Size
32KB	2Kx8	2Kx1	8Kx8 x4	8MB
64KB	4Kx8	4Kx1	8Kx8 x8	16MB
128KB	8Kx8	8Kx1	32Kx8 x4	32MB
256KB	16Kx8	16Kx1	32Kx8 x8	64MB
512KB	32Kx8	32Kx1	128Kx8 x4	128MB
1M	64Kx8	64Kx1	128Kx8x8	128MB

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(A) 8-bit wide TAG address field



(B) 7-bit wide TAG address field

Cache Size	Tag RAM + Alter RAM	Data RAM	Cacheable Size
32KB	2Kx8	8Kx8 x4	4MB
64KB	4Kx8	8Kx8 x8	8MB
128KB	8Kx8	32Kx8 x4	16MB
256KB	16Kx8	32Kx8 x8	32MB
512KB	32Kx8	128Kx8 x4	64MB
1M	64Kx8	128Kx8x8	128MB

The cacheable DRAM size is determined by cache size because the tag address field is always 8-bit wide. The on-board memory beyond the cacheable size is not cacheable. It is still cacheable for the 80486 internal cache.

2.1.6 Cache Speed Options

The external cache can be configured as non-interleaved or two-bank interleaved. Two-bank interleaved cache can use slower cache data RAMs but needs more data RAM chips.

The SiS85C471 provides four cache read speed options : 2-1-1-1, 3-1-1-1, 2-2-2-2 and 3-2-2-2, and two options for cache write cycles : 2T or 3T. The cache read speed x-y-y-y is selected via bit 7 of configuration register 50 (x) and bit 0 of configuration register 51 (y). The 2T cache write is applicable only when the first cycle of a burst cache read is also set to 2T (2-1-1-1 or 2-2-2-2).

The following is the table of cache configurations and the suggested speeds of the SRAMs in implementing the cache data RAMs for various CPU speeds.

Cache Configuration	25MHz CPU	33MHz CPU	40MHz CPU	50MHz CPU
2-1-2 Interleave (*1)	-35 (*2)	-20	-12	
2-1-2 Non-interleave	-25	-15		
2-1-3 Interleave	-40	-25	-20	
2-1-3 Non-interleave	-25	-15		
3-1-3 Interleave	-45	-25	-20	-12
3-1-3 Non-interleave	-25	-15		
2-2-2 Non-interleave	-35	-20	-12	
2-2-3 Non-interleave	-40	-25	-20	
3-2-3 Non-interleave	-65	-45	-35	-25
3-2-3 Interleave	-80	-55	-45	-30

Note: *1. x-y-z means x-y-y-y burst read and zT write cycle. *2. -m means the access speed of SRAMs in ns.

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The following is the table of cache configu-rations and suggested speeds of the SRAMs in implementing the cache tag and alter RAMs for various CPU speeds.

Cache Configuration	25MHz CPU	33MHz CPU	40MHz CPU	50MHz CPU
2-X-2	-25	-20	-12	
2-X-3	-35	-25	-15	
3-X-3	-45	-35	-25	-20

Note: X represents either 1T or 2T cycles.

2.1.7 Non-Cacheable Regions

In some applications, users prefer a block of memory not to be cached. The SiS85C471 provides two programmable non-cacheable regions to serve this function.

Only the on-board DRAMs directly controlled by SiS85C471 are cacheable. The memory residing on the AT bus is non-cacheable. When a memory space is mapped by both the on-board DRAMs and AT add-in memory, the CPU accesses will be conducted to the on-board DRAMs.

If the AT add-in memory is to be accessed instead of the on-board DRAMs in the overlapped memory space, the two non-cacheable regions can be used to disable the on-board DRAMs in the programmed space.

The sizes and starting addresses of the two non-cacheable regions are programmable in the configuration registers 54, 55, 56 and 57. The validity of the starting address bits depends on the size of the related non-cacheable region as shown in the table below.

Size	A23	A22	A21	A20	A19	A18	A17	A16
64K	V	V	V	V	V	V	V	V
128K	V	V	V	V	V	V	V	Х
256K	V	V	V	V	V	V	Х	Х
512K	V	V	V	V	V	Х	Х	Х
1M	V	V	V	V	Х	Х	Х	Х
2M	V	V	V	Х	Х	Х	Х	Х
4M	V	V	Х	Х	Х	Х	Х	Х

V = Valid

X = Don't Care



2.1.8 Cache Initialization

The second level cache supported by SiS85C471 does NOT provide the valid bits for the data lines. All the cache data are assumed valid once the cache is enabled. All the cache lines must be filled with valid data before the cache enable bit is turned on. The cache initialization can be done through sequential reads to a block of on-board DRAMs which is equal to or larger than the cache in size.

2.2 DRAM Controller

2.2.1 DRAM Speed Options

The SiS85C471 provides 4 read and 2 write speed options in the configuration register. A table of page hit cycle times of all the possible speed configurations is listed as follows:

	Read	486 Burst Read	<u>Write</u>
Fastest	3	3-2-2-2	2
Faster	4	4-3-3-3	2/3
Slower	5	5-4-4-4	2/3
Slowest	6	6-5-5-5	4

Note: The unit of the above table is in T cycles.

There will be plenty of timing margin if "Fastest" is used for 25MHz 80486, "Faster" for 33MHz 80486, "Slower" for 40MHz 80486, and "Slowest" for 50MHz 80486. The table below shows the DRAM access timing for different speed configurations.

2.2.2 DRAM Size Configuration

The SiS85C471 supports 53 DRAM configurations in 4 banks. Besides the traditional 256K/1M/4M xN DRAMs, the new 512K /2M/8M/16M xN DRAMs are also supported.

Refresh

In the original PC/AT design, the CPU is held off (i.e. HLDA asserted) during the DRAM refresh cycles. It happens once every 15us and takes at least 0.5us for each occurrance.

In SiS85C471, refresh can be selected to hold the CPU or not by setting bit 5 of the configuration register 58.

The DRAM speeds are becoming faster and the time needed for each refresh cycle is getting shorter. For example, the refresh cycle time for 100ns DRAMs is 180ns minimum. In a system with cache, most of the CPU accesses are referred to the cache, so the DRAM usage (percent of time the DRAMs are accessed by the CPU) is significantly reduced.



DRAM Access Timing

	Fastest	Faster	Slower	Slowest	
Trcd	1.5T	2T	2T	3T	RAS-to-CAS delay
Tcas	1.5T	2T	3T	3T	Read CAS pulse width
Trp	3T	3T	4T	5T	RAS precharge
Тср	0.5T	1T	1T	2T	CAS precharge

In the SiS85C471, the main memory refresh is independent of the AT-bus refresh so the cycle time is shorter (not necessary to follow the standard AT-bus timing). When doing the main memory refresh, the CPU is NOT held off so it may execute the program in the cache. If the CPU accesses the main memory while the refresh cycle is going, the access will be pending until the refresh cycle is finished.

The following table lists the refresh-related RAS timings of the on-board DRAMs :

	Fastest	<u>Faster</u>	<u>Slower</u>	<u>Slowest</u>
RAS	3T	3T	4T	5T
pre-charge	;			
RAS active	e 3T	4T	4T	5T

If hidden refresh is selected on the AT bus, the AT bus refresh cycles are issued every 15us when there is no access from the CPU, the local bus masters, the DMA controllers, or the bus master on the AT bus. The CPU will not feel the existence of the AT bus refresh cycles unless it issues an AT bus cycle or cache miss cycle while the refresh cycle is going on. The controller arbitrates among the CPU AT cycle, the DMA/master request, and the AT bus refresh cycle so that they can be executed one after another when more than one intend to use the AT bus at the same time.

The SiS85C471 has a slow refresh feature to cut the refresh frequency down to 1/4. It should be selected only when the system is equipped with slow-refresh DRAMs.

The refresh scheme of the CPU local DRAMs is CAS-before-RAS refresh. The CASes go active at least one T before the RASes in local memory refresh cycles.

To reduce the power noise caused by the refresh cycles, the RASes of the odd banks go active one T after the RASes of the even banks. It is called the "staggered refresh".

2.2.3 Shadow RAM

The Memory space 0A0000-0FFFFFh is reserved for the video RAM, the I/O and system BIOS ROMs. Accesses to this area should not be conducted to the main memory in standard PC/AT systems. Since the speed of the DRAMs is significantly faster than that of the ROMs, the overall system performance can be improved if contents of the BIOS ROMs are copied to the unused DRAM area (0A0000- 0FFFFFh), and the CPU accesses to this area are conducted to the DRAMs instead of to the BIOS ROMs. This is called the "Shadow RAM".

The SiS85C471 provides shadows to 0C0000-0EFFFh in 32KB granularity and shadow to 0F0000-0FFFFh. The shadow RAMs are non-cacheable by default. The shadow RAMs in C0000-C7FFFh and F0000-FFFFFh can be programmed to being cacheable.

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2.2.4 256KB Relocation

The SiS85C471 provides the 256KB DRAM relocation from 0A0000-0BFFFFh and 0D0000-0EFFFFh to the top of the configured DRAM.

This function works for the DRAM sizes of 1MB, 2MB, 4MB, 6MB and 8MB when the shadowing of D and E segments is disabled.

2.2.5 72-pin SIMM Module Support

The SiS85C471 supports 72-pin double-sided SIMM modules. Please refer to Register 59 bit 5-0 on page 27 for details.

2.3 ROM/Flash ROM Support

The SiS85C471 provides a chip select signal for the system BIOS ROM. The memory space assigned to the ROM/Flash ROM is the highest 64/128KB of the real (1MB) and the protected (4GB) address modes of the 80486/P24D/P24T/P24C CPUs.

The system BIOS ROM can be shadowed to the DRAMs to improve performance. When the RAM shadowing feature is turned on, the accesses to the system BIOS with addresses below 100000h will be channeled to the DRAMs.

2.4 Fast A20GATE And CPU Reset/Port 92h

In the original PC/AT design, the A20GATE and CPU Reset (RC) are controlled by the 8042 keyboard controller to switch the CPU between the real and protected address modes and to warm boot the system. The operation of 8042 is slow. If address mode switching happens frequently, execution speed will be affected.

The SiS85C471 provides an 8042 emulation to generate the A20GATE and CPU reset signals in hardware. This feature is software transparent.

The SiS85C471 also provides a control port, I/O port hex 0092, to generate the A20GATE and the CPU reset. The following shows the definitions of bit 1 and bit 0 of the port 092h that are used for the generation of those two signals.

- Bit 1: This bit is internally OR'ed with the FAST_A20_GATE. Writing an "1" to this bit will force A20M to go high active. Upon reset, this bit goes low.
- Bit 0: This bit can be set to "0" by a CPU reset or a IO write operation. A transition of this bit from "0" to "1" will have the INIT signal go active. The minimum delay from the transition of this to the INIT active is 2 to 6 μs.

2.5 Local Bus Support

The SiS85C471 uses LBD* (Local Bus Device) and LRDY* (Local Bus Device Ready) pins to implement Local Bus Device Architecture such as Weitek 3167/4167 and VESA VL-Bus devices.

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When there are more than one local bus devices, their LBD* signals should be "ANDed" together before connecting to the SiS85C471.

The SiS85C471 samples the LBD* input at the end of T2 when DRAM speed is set to "FASTEST" or "FASTER", and at the end of T3 when DRAM speed is "SLOWER" or "SLOWEST". The LBD* pin should be asserted before the sampling point if the current cycle is a local bus cycle. Bit 1 of Register 58 can be programmed to overwrite the sampling point described above.

2.5.1 VESA VL-Bus Interface

The SiS85C471 provides VESA local bus supports as follows :

A. Local bus device is accessed by CPU :

- •When a local bus device decodes the bus definition/address and determines this is its cycle at the start of a CPU bus cycle, it should assert LBD* to inform the SiS85C471 this is a local bus device cycle.
- •The local bus cycle can be terminated in two ways :
 - 1. The local bus device asserts LRDY* to the SiS85C471. The SiS85C471 will generate the CPURDY* by either synchronizing the LRDY* with the CPU clock (synchronous mode) or passing LRDY* directly to the output buffer (transparent mode) determined by Bit 0 of Register 58 being 0 (default) or 1.
 - 2. The local bus device can assert BRDY* to indicate the burst mode transfer support. The SiS85C471 also monitors BRDY* when LBD* is detected asserted. When the SiS85C471 detects that both BLAST* from the CPU and BRDY* from the local bus device are asserted, the SiS85C471 will end the burst transfer cycle.
- •BS16* support: If the local bus device is capable of doing 16-bit transfers only, it should assert BS16* to the CPU to indicate that another cycle may be necessary.

B. Local bus master cycles

- •The SiS85C471 supports two local bus masters. When a local bus master needs to take over the bus, it issues bus request signal to the SiS85C471. The SiS85C471 waits until there is no other local bus cycle pending before issuing the bus grant signal to indicate that the local bus master can start to access the system targets. The local bus masters can access all the system resources including on-board memory, the ISA-bus devices, and the local bus targets.
- •The local bus master can perform burst mode transfers while accessing on-board memory or a local bus target that supports burst transfers. After detecting three BRDY*s, the local bus master issues BLAST* to indicate the last burst cycle. The local bus masters which do not wish to burst, must drive BLAST* low when they own the bus.

C. DMA/ISA master accesses local bus target

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- •When the address coming from ISA bus in a DMA or an ISA bus master cycle selects a local bus target.
- •The ADS*, M/IO*, and W/R* are driven by the SiS85C471 in this cycle and the timing is designed to meet the spec. of VESA local bus.
- •The local bus target asserts LBD* to indicate that the local bus target is selected.
- •The SiS85C471 deasserts IORDY low to keep the cycle active until the LRDY* is asserted low by the local bus target. then the SiS85C471 asserts IORDY high to terminate the cycle.
- •ISA command will be negated at least 1 AT clock after IORDY being asserted. In a local bus read cycle, the data will be invalid after CPURDY* (RDYRTN*) is asserted. The SiS85C471 latches data and keeps the data valid until the ISA bus command is negated.

2.6 Turbo Switch

The 486 systems are fast, so it is possible for them to run into problems with some applications. The SiS85C471 offers a De-Turbo function that can be controlled through a hardware switch or software programming. When the De-Turbo function is ON, the system speed can be reduced by 1/3 or 2/3 selected by bit 4 of the configuration register 58.

2.7 Advanced Clock

To increase the setup time margins of the chip output buffers in a high speed system, the SiS85C471's clock input XFCLK, the "Advanced clock", leads the CPU clock by 3~5 ns. The cache read control signals, the local bus control signals, and others can be issued early to increase the margin of cache data RAM access time and the setup time.

2.8 Clock Generation

The CPU clock speed is too fast for slow AT bus. To overcome this problem, the SiS85C471 provides a flexible software- controlled selections of the clock used for the AT bus state machine. The SiS85C471 operates the AT bus state machine at the AT bus clock which is determined by the configuration register and can be selected as 1/2, 1/3, 1/4, 1/5, 1/6, 1/8 or 1/10 of the input clock, or 7.159 MHz.

Whenever the configuration is changed, the clock frequency switches accordingly with glitch-free transition.

2.9 AT Bus State Machine

The SiS85C471 starts an AT bus cycle when the current cycle is not a local bus or a local memory cycle. The SiS85C471 asserts BS16* to the CPU or the local bus master and starts driving BALE signal in the AT-TS state.

It then enters into the command cycle AT-TC and provides the timing signals for the AT bus cycle and terminates the cycle by asserting CPURDY* signal.

To determine the bus size, MEMCS16* signal is sampled at the falling edge of BALE during memory cycle or IOCS16* is sampled at the falling edge of BALE after the command is active

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in an I/O cycle. The command cycle is terminated only when IORDY is active and all programmed wait states have been executed.

The period of command cycle is selected by the configuration register. For 16-bit transfers, the default is 1 wait state and can be selected as 2 wait states. For 8-bit transfer, the default is 4 wait states and can be selected as 5 wait states. No command delay is inserted for 16-bit memory cycles and 1/2 SYSCLK command delay is inserted for other cycles.

IORDY is sampled at the start of every AT-TC state. The command cycle will not complete until all programmed wait states have be executed and IORDY is sampled high. If ZWS* is detected LOW at the middle of the AT-TC state, the current AT cycle will be terminated immediately.

During a read cycle, the data read from a device may be lost after the command completes. The SiS85C471 latches the data immediately after the read command is inactive and holds the data until the AT cycle ends. The "Read Latch" function is active for all AT bus read cycles, except during DMA, ISA bus Master, or local RAM read cycles.

The shortest command recovery time is two AT clock cycles in this chip. It can be too short for some I/O devices. A configuration register is provided to selected the I/O command recovery time for 16-bit transfers and for 8-bit transfers. Please refer to the configuration register 61 description for detail.

2.10 Data Conversion Logic

If both MEMCS16* and IOCS16* are sampled negated, the current cycle is an 8-bit cycle. The AT state machine performs data conversion if the CPU executes a 16-bit read or write during an 8-bit transfer. Besides data conversion, the data are also swapped if necessary. In DMA or ISA Master cycles, data swapping is also processed if necessary. The system checks the command, address, and related control signals and then arranges required swapping.

BE0*-BE3* can not be used to select the devices on AT bus directly. BE0*-BE3* are inputs in AT cycles to generate SA1, SA0, and BHE* signals. In a DMA cycle, BE0*-BE3* are generated from SA1 and SA0 to access the local memory. The SiS85C471 checks these four byte enable signals in an AT cycle and determines if it is a 16-bit cycle and whether data conversion should be performed.

The SiS85C471 separates a 16-bit read or write operation into two 8-bit transfers and drives SA0 high in the second cycle. In the meanwhile, the SiS85C471 executes the data swapping process among the 32-bit, 16-bit and 8-bit data buses.

2.11 Port B Register/NMI Logic

The SiS85C471 provides accesses to Port B defined by IBM PC/AT. The bit definitions of Port B register are as follows :

<u>Bit</u>	<u>Contents</u>				
0	GATE2 - Timer 2 Gate				
1	SPKEN - Speaker Data				
2	PCKEN - Parity Check Enable				
		~	 	~	



- 3 IOCHCKEN I/O Channel Check Enable
- 4 REFRESH Refresh Detect
- 5 OUT2 Timer 2 Out
- 6 IOCHCK I/O Channel Check
- 7 PCK Parity Check

The NMI logic in the SiS85C471 enables and latches the I/O or parity error to generate a nonmaskable interrupt to the CPU if NMI is enabled. NMI is enabled when bit 7 of port 70h is clear to 0. NMI is disabled if it is set to 1.

2.12 Bus Buffer Control Logic

During an AT-bus read cycle, the data from the responding device are latched immediately after the read command is inactive and are held stable till the end of the AT cycle.

The SiS85C471 provides 16-bit to 8-bit or 8-bit to 16-bit data bus conversion in AT cycles. In DMA cycles, 32-bit, 16-bit and 8-bit data bus conversions are provided.

2.13 Parity Generation/Detection

During memory write cycles, the SiS85C471 generates even parity for each of the four bytes. The parity bits PD0- PD3 are written to the parity memory in the system DRAMs. During memory read cycles, the SiS85C471 checks for even parity for each byte read. If odd parity is detected, the SiS85C471 flags a parity error. The SiS85C471 detects the error and generates NMI when enabled. The parity error can be cleared by programming parity check disable, which is defined by Bit 2 of port B register.

2.14 Peripheral Controllers

The SiS85C471 contains Peripheral Controllers which include two 8237 DMA Controllers, a 74LS612 Mapper, two 8259 Interrupt Controllers, and an 8254 Counter/Timer.

2.15 DMA Controllers

Two DMA controllers are connected in such a manner as to provide the user with four DMA channels (DMA1) for 8-bit transfers and three DMA channels (DMA2) for 16-bit transfers (the first 16-bit DMA channel is used for cascading to DMA1). The DMA address mapper, the 74LS612, is used to drive the upper address lines during DMA cycles.

2.16 Interrupt Controllers

Two interrupt controllers, namely INTC1 and INTC2, are provided in the SiS85C471. Each controller supports 8 channels of interrupts, so in total, the SiS85C471 supports 16 levels of interrupts. Of the 16 channels, two channels are connected internally to support internal devices, allowing 14 user-definable interrupt channels. The two internally connected channels are :

Channel 0 -Counter/Timer Counter 0 Interrupt Channel 2 -Cascade to Slave Interrupt Controller (INTC2)

2.17 Counter/Timer

The Counter/Timer (CTC) subsystem contains three independent counters. The clock input of each counter is connected to a clock of 1.19MHz which is derived from dividing the

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14.318MHz input by 12. Counter 0 is connected to Interrupt 0 of INTC1. It is used as a multilevel interrupt to the system for such task as time keeping or task-switching. Counter 1 can be programmed to generate pulses or square waves for used by external devices and Counter 2 is a full function Counter/Timer which has a gate input for controlling the internal counter. This counter can be used as an internal counter, a timer, or as a gated rate or pulse generator.

2.18 Clock and Wait State Control

The Clock and Wait State Control subsystem performs four functions : control of the DMA command width; control of the CPU read cycle length; control of the CPU write cycle length and selection of the DMA clock rate. All the functions are user selectable by writing to the Configuration Register located at address 023h.

Writing or reading this register is accom-plished by first writing a 01h to location 022h to select the Configuration Register. After the Configuration Register 01h is selected, a write or read cycle can be issued to access the data register located at 023h.

2.19 Peripheral Controllers Address Map

DMA Controller Address Map

DMA1	DMA2	XIOR*	XIOW*	Flip Flop	Register Function
000h	0C0h	0	1	0	Read channel 0 current address low byte
		0	1	1	Read channel 0 current address high byte
		1	0	0	Write channel 0 base and current address low byte
		1	0	1	Write channel 0 base and current address high byte
001h	0C2h	0	1	0	Read channel 0 current word count low byte
		0	1	1	Read channel 0 current word count high byte
		1	0	0	Write channel 0 base and current word count low byte
		1	0	1	Write channel 0 base and current word count high byte
002h	0C4h	0	1	0	Read channel 1 current address low byte
		0	1	1	Read channel 1 current address high byte
		1	0	0	Write channel 1 base and current address low byte
		1	0	1	Write channel 1 base and current address high byte
003h	0C6h	0	1	0	Read channel 1 current word count low byte
		0	1	1	Read channel 1 current word count high byte
		1	0	0	Write channel 1 base and current word count low byte
		1	0	1	Write channel 1 base and current word count high byte
004h	0C8h	0	1	0	Read channel 2 current address low byte
		0	1	1	Read channel 2 current address high byte
		1	0	0	Write channel 2 base and current address low byte
		1	0	1	Write channel 2 base and current address high byte
005h	0CAh	0	1	0	Read channel 2 current word count low byte
		0	1	1	Read channel 2 current word count high byte
		1	0	0	Write channel 2 base and current word count low byte
		1	0	1	Write channel 2 base and current word count high byte
006h	0CCh	0	1	0	Read channel 3 current address low byte
		0	1	1	Read channel 3 current address high byte
		1	0	0	Write channel 3 base and current address low byte
		1	0	1	Write channel 3 base and current address high byte

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007h	0CEh	0	1	0	Read channel 3 current word count low byte	
		0	1	1	Read channel 3 current word count high byte	
		1	0	0	Write channel 3 base and current word count low byte	
		1	0	1	Write channel 3 base and current word count high byte	

An internal flip-flop is used to supplement the addressing of the Count and Address registers. This flip-flop selects between high and low bytes of these registers and toggles each time a read or write occurs to any of these registers.

DMA1	DMA2	XIOR*	XIOW*	Flip Flop	Register Function
008h	0D0h	0	1	Х	Read status register
		1	0	Х	Write command register
009h	0D2h	0	1	Х	Read DMA request register
		1	0	Х	Write DMA request register
00Ah	0D4h	0	1	Х	Read mode register
		1	0	Х	Write single bit DMA request mask
					register
00Bh	0D6h	0	1	Х	Read mode register
		1	0	Х	Write mode register
00Ch	0D8h	0	1	Х	Set byte pointer flip-flop
		1	0	Х	Clear byte pointer flip-flop
00Dh	0DAh	0	1	Х	Read temporary register
					Master clear
00Eh	0DCh	0	1	Х	Clear mode register counter
		1	0	Х	Clear all DMA request mask register bits
00Fh	0DEh	0	1	Х	Read all DMA request mask register bits
		1	0	Х	Write all DMA request mask register bits

DMA Controllers Address Map (continued)



DMA Address Extension Register Map

Address	Register Function
080h	Unused
081h	8-bit DMA Channel 2 (DACK2)
082h	8-bit DMA Channel 3 (DACK3)
083h	8-bit DMA Channel 1 (DACK1)
084h	Unused
085h	Unused
086h	Unused
087h	8-bit DMA Channel 0 (DACK0)
088h	Unused
089h	16-bit DMA Channel 2 (DACK6)
08Ah	16-bit DMA Channel 3 (DACK7)
08Bh	16-bit DMA Channel 1 (DACK5)
08Ch	Unused
08Dh	Unused
08Eh	Unused
08Fh	Refresh cycle

Interrupt Controller Address Map

Register	Туре	I/O Port	b7	b6	b5	b4	b3	b2	b1	b0
ICW1	WRO	20h (A0h)	Х	х	Х	SI	LTM	Х	SM	Х
ICW2	WRO	21h (A1h)	V7	V6	V5	V4	V3	Х	Х	Х
ICW3	WRO	21h	S7	S6	S5	S5	S3	S2	S1	S0
ICW3	WRO	A1h	0	0	0	0	0	ID2	ID1	ID0
ICW4	WRO	21h (A1h)	Х	Х	Х	EMI	Х	Х	AEOI	Х
OCW1	RD/WR	21h (A1h)	M7	M6	M5	M4	M3	M2	M1	MO
OCW2	WRO	20h (A0h)	R	SL	EOI	SI	2/3	L2	L1	L0
OCW3	WRO	20h (A0h)	0	ESSM	SMM	SI	2/3	ΡM	RR	RIS
IR	RDO	20h (A0h)	IR7	IR6	IR5	IR4	IR3	IR2	IR1	IR0
IS	RDO	20h (A0h)	IS7	IS6	IS5	IS4	IS3	IS2	IS1	IS0

Note :

WRO =	Write only register
-------	---------------------

RDO = Read only register

- RD/WR = Read/Write register
- X = Don't care

Counter/Timer Address Map

<u>Address</u>	Function
040h	Counter 0 read/write
041h	Counter 1 read/write
042h	Counter 2 read/write
043h	Control register write only

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2.20 Green PC Function

In order to support Intel, Cyrix SMI functions, the SiS85C471 provides SMI* (pin 93), STPCLK* (pin 94) and SMIACT*/ SMADS* (pin 84) for power saving. To support AMD Am486DXL SMI function, the SiS85C471 also provides SMI*(pin93) and SMIADS*(pin 84) for power saving.

The basic concept of green function depends on system timer reloading. If no system event happened and the timer reaches count, the SiS85C471 enters SMM or slows down CPU speed. If the processor of the system does not support SMI*, STPCLK* pin can still be used to reduce the CPU speed, but additional application circuit is necessary to reduce the CPU speed by 10% descending.

The SiS85C471 provides two timers, the system event timer and the I/O event timer, to support the GREEN PC functions. Each timer can be used to monitor different events. All the devices therefore can be programmed to enter standby mode at different time zones. Each device could be independent to other devices in entering or waking up from the standby mode. Once a device is entering the standby mode, the I/O timer will be reloaded for the next device to enter the standby mode.

The selected device will enter the standby mode or the off mode when a time out of the corresponding timer happens. The SMI handler will enable the corresponding bit of the Register 68 if the device enters the standby mode. The corresponding bit of the Register 69 will be set when wake-up condition for the device in standby mode is detected. The device then will return back to normal mode by the SMI handler.

The SiS85C471 also supports the clock throttling mode. If the throttling mode is enabled, the STPCLK* signal will go inactive while an IRQ0 request is served. Hence the operating system timer will not stop while the CPU operation is stopped in the suspend mode.

Bit 7 of register 5B is used to enable/disable SMM. Registers 5C-5E define un-monitored interrupt vectors. Register 63 defines the SM-RAM address and stop clock condition. Registers 64-65 are used to define Software_SMI address. Registers 66 and 67 are used to select IRQn to break the stop clock. Register 6A defines system management output port SMOUT 7-0. System timer is defined in registers 6D-6F.



3. CONFIGURATION REGISTERS

There are several configuration registers in the SiS85C471. An indexing scheme is used to access the registers. Port 22h is the index register and port 23h is the data register.

The configuration registers are accessed by first writing the index to port 22h and immediately followed by a read from or a write to port 23h. The index is reset after each data access. Every data access to port 23h must be preceded by an index write to port 22h, even if the same register is being accessed. All the reserved bits should be set to the value indicated in the register table for future compatibility purpose.

The contents of the configuration registers are listed in the following sections.

System Hardware Configuration

Six pins in the SiS85C471 are used for trapping purpose to identify the hardware configurations at the power-up stage (PWRGD is low).

The pin is defined to be 1 if a pull up resistor is used; and it is 0 if a pull down resistor is used. A pull up or pull down resistor of 2.2k is adequate for the trapping purpose. The definitions of the pins are listed below :

3.1 Hardware Trap Definition

DACK1* DACK0* CPU Type Select

-	-	
0	0	Reserved
•		
0	1	M7/Am486DXL/Am486DXL2
1	0	486DX2/DX/SX/SL Enhanced/P24C
I	U	
1	1	P24D/P24T
	1	1 240/1 241

DACK2*

- 1 Cache system
- 0 Non-cache system

DACK3*

471 internal operating frequency = XFCLK
 471 internal operating frequency = 1/2 XFCLK

(For more details, please refer to the application circuit.)

SPK

- 1 Signal DACKn defined as master request and grand signal of VESA bus
- 0 Retrieve DACKn definition

SMOUT0 (In Cache System)

- 0 Pin 176 = RAS6* and Pin 177 = RAS7* (only for the systems with the 85C407)
- 1 Pin 176 = MPXS1 and Pin 177 = MPXS0





3.2 Configuration Registers

Register 50 (index50) Hardware Default = 00

bit 7, 6 DRAM Speed (See DRAM Speed Options on page 10)

- 00 : Slowest
- 01 : Slower
- 10 : Faster
- 11 : Fastest

Bit 7 also defines the first transfer of burst cache read and burst cache write cycle time: 0/1 : 3T/2T

bit 5 DRAM Write CAS Pulse Width

0:2T 1:1T

bit 4 Support CPU internal cache write back control

- 0 : Disabled
- 1 : Enabled

When using P24T/D or M6/M7, this bit may be programmed. Otherwise, this bit should be set to 0.

bit 3 External cache write back enable

- 0 : Disabled (Write Through)
- 1 : Enabled (Write Back)

bit 2 Pin 138 multiplex output control

- 0 : RAS3*
- 1 : MA11

When 16M SIMM DRAM configuration is set, pin 138 functions as MA11 and bank 3 supports no DRAM.

- bit 1 Burst write enable
 - 0 : Disabled
 - 1 : Enabled

When register 50 bit 4 is set, this bit may be programmed. Otherwise, this bit should be set to 0.

bit 0 INIT active enable 0 : Disabled 1 : Enabled When using P24T/D/C, M6/M7, SL Enhanced 486, this bit should be set to 1.



Register 51 (index 51) Hardware Default = 00

	bit 7	Cache Enable 0 : Disabled 1 : Enabled
	bit 6,5,4	Cache size 000 : 32KB 001 : 64KB 010 : 128KB 011 : 256KB 100 : 512KB 101 : 1MB
	bit 3	Cache Interleave Enable 0 : Disabled 1 : Enabled If there are two banks cache, this bit should be set to 1.
	bit 2	Cache On/Off 0 : Off 1 : On When this bit is disabled, all memory access will be fetched from DRAM directly instead of from cache.
	bit 1	Single / Burst Cache Write Cycle For single cache write cycle 0 : 3T 1 : 2T For burst cache write cycle, it denotes the last three transfer cycle 0 : 2T 1 : 1T
	bit 0	Cache Burst Read Cycle 0 : 1T 1 : 2T
R	Register 52 (ii	ndex 52) Hardware Default = 00
	bit 7	Shadow RAM Read Enable
	bit 6	Shadow RAM Write Protection Enable
	bit 5	E8000h - EFFFFh Shadow RAM Enable
	bit 4	E0000h - E7FFFh Shadow RAM Enable

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bit 3	D8000h - DFFFFh Shadow RAM Enable
bit 2	D0000h - D7FFFh Shadow RAM Enable
bit 1	C8000h - CFFFFh Shadow RAM Enable
bit 0	C0000h - C7FFFh Shadow RAM Enable
bit 0-7	0 : Disabled 1 : Enabled
Register 53 (in	ndex 53) Hardware Default = 00
bit 7	System BIOS ROM Size 0 : 64K 1 : 128K
bit 6	Combine System BIOS with C0000h - C7FFFh region for ROM area 0 : Disabled 1 : Enabled
bit 5	F0000h ~ FFFFFh Shadow RAM Cacheable 0 : Non-Cacheable 1 : Cacheable
bit 4	C0000h ~ C7FFFh Shadow RAM Cacheable 0 : Non-Cacheable 1 : Cacheable
bit 3, 2, 1	DMA Cycle Up to 128MB Program A26, A25 and A24
bit 0	Data Parity check enable 0 : Disabled 1 : Enabled
Register 54 (i	ndex 54) Hardware Default = 00
bit 7	Allocation of Non-cacheable Area #1 0 : Local DRAM 1 : AT Bus, local DRAM disabled





bit 6~4	Size of Non-Cacheable Area #1 (within 16MB) 000 : 0KB (disabled) 001 : 64KB 010 : 128KB 011 : 256KB 100 : 512KB 101 : 1MB 110 : 2MB 111 : 4MB
bit 3	Allocation of Non-Cacheable Area #2 0 : Local DRAM 1 : AT Bus, local DRAM disabled
bit 2~0	Size of Non-Cacheable Area #2 (within 128MB) 000 : 0KB (disabled) 001 : 64KB 010 : 128KB 011 : 256KB 100 : 512KB 101 : 1MB 110 : 2MB 111 : 4MB
Register 55 (i	ndex 55) Hardware Default = 00
bit 7~0	A23~A16 of Non-Cacheable Area #1 (within 16MB)
Register 56 (i	ndex 56) Hardware Default = 00
bit 7~0	A23~A16 of Non-Cacheable Area #2 (within 128MB)
Register 57 (i	ndex 57) Hardware Default = 00
bit 7, 6, 5	A26, A25 and A24 of Non-Cacheable Area #2
bit 4	Fast Reset Emulation Enable 0 : Disabled 1 : Enabled
bit 3	Fast Reset Latency Control 0 : 2us

1 : 6us





bit 2	Slow Refresh Enable (1:4) 0 : Normal Refresh 1 : Slow Refresh
bit 1	Gate A20 Emulation Enable 0 : Disabled 1 : Enabled
bit 0	Cache Sizing Enable 0 : Normal Operation 1 : Always Cache hit
Register 58 (ir	ndex 58) Hardware Default = 00
bit 7	Slow CPU (below 25MHz) Enable 0 : Disabled 1 : Enabled
bit 6	DRAM Write Cycle 0 : 1 wait state 1 : 0 wait state
bit 5	Refresh Cycle Hold CPU 0 : Enabled 1 : Disabled (set Hidden Refresh)
bit 4	De-turbo Hold Time (Every 12us) 0 : Hold 4us 1 : Hold 8us
bit 3	Reserved and should be written with 0.
bit 2	Combine System BIOS with C8000h - CFFFFh region for ROM area 0 : Disabled 1 : Enabled
bit 1	Latch Local Bus Device (LDEV*) in T2/T3 0 : T3 1 : T2
bit 0	Select Local Bus Ready (LRDY*) 0 : Synchronize in next clock 1 : Transparent



Register 59 (index 59) Hardware Default =00

- bit 7 De-Turbo On / Off
 - 0 : Turbo
 - 1 : De-Turbo

bit 6

De-Turbo Switch Enable

0 : De-Turbo switch enabled

1 : Always turbo, ignore the status of turbo switch

bit 5 - 0 DRAM Size Configuration (note: S = Single side, D = Double side)

	Bank-0	Bank-1	Bank-2	Bank-3	Total
000000	256K*36-S				1MB
000001	256K*36-S	256K*36-S			2MB
000010	256K*36-S	256K*36-S	512K*36-D		4MB
000011	256K*36-S	256K*36-S	1M*36-S		6MB
000100	256K*36-S	256K*36-S	512K*36-D	1M*36-S	8MB
000101	256K*36-S	256K*36-S	1M*36-S	1M*36-S	10MB
000110	256K*36-S	256K*36-S	4M*36-S		18MB
000111	512K*36-D				2MB
001000	512K*36-D	512K*36-D			4MB
001001	512K*36-D	1M*36-S			6MB
001010	512K*36-D	512K*36-D	1M*36-S		8MB
001011	512K*36-D	512K*36-D	1M*36-S	1M*36-S	12MB
001100	512K*36-D	4M*36-S			18MB
001101	512K*36-D	512K*36-D	4M*36-S		20MB
001110	512K*36-D	512K*36-D	1M*36-S	4M*36-S	24MB
001111	512K*36-D	512K*36-D	4M*36-S	4M*36-S	36MB
010000	1M*36-S				4MB
010001	1M*36-S	1M*36-S			8MB
010010	1M*36-S	1M*36-S	1M*36-S		12MB
010011	1M*36-S	1M*36-S	1M*36-S	1M*36-S	16MB
010100	1M*36-S	4M*36-S			20MB
010101	1M*36-S	1M*36-S	4M*36-S		24MB
010110	1M*36-S	4M*36-S	4M*36-S		36MB
010111	1M*36-S	1M*36-S	4M*36-S	4M*36-S	40MB
011000	2M*36-D				8MB
011001	2M*36-D	2M*36-D			16MB
011010	2M*36-D	2M*36-D	2M*36-D		24MB
011011		2M*36-D	2M*36-D	2M*36-D	32MB
011100	4M*36-S				16MB
011101		4M*36-S			32MB
011110	4M*36-S	4M*36-S	4M*36-S		48MB
011111		4M*36-S	4M*36-S	4M*36-S	64MB
100000		1M*36-S			5MB
100001		4M*36-S			17MB
100010	256K*36-S	16M*36-S			65MB
100011		2M*36-D			12MB
100100	1M*36-S	16M*36-S			68MB
100101	1M*36-S	1M*36-S	16M*36-S		72MB
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100110	4M*36-S	16M*36-S			80MB
100111	4M*36-S	4M*36-S	16M*36-S		96MB
101000	16M*36-S				64MB
101001	16M*36-S	16M*36-S			128MB
101010	1M*36-S	8M*36-D			36MB
101011	1M*36-S	8M*36-D	8M*36-D		68MB
101100	1M*36-S	1M*36-S	8M*36-D		40MB
101101	1M*36-S	1M*36-S	8M*36-D	8M*36-D	72MB
101110	4M*36-S	8M*36-D			48MB
101111	4M*36-S	8M*36-D	8M*36-D		80MB
110000	4M*36-S	4M*36-S	8M*36-D		64MB
110001	4M*36-S	4M*36-S	8M*36-D	8M*36-D	96MB
110010	8M*36-D				32MB
110011	8M*36-D	8M*36-D			64MB
110100	8M*36-D	8M*36-D	8M*36-D		96MB
110101	8M*36-D	8M*36-D	8M*36-D	8M*36-D	128MB
110110	1M*36-S	2M*36-D	2M*36-D		20MB
110111	1M*36-S	2M*36-D	2M*36-D	2M*36-D	28MB
111000	1M*36-S	1M*36-S	2M*36-D		16MB
111001	1M*36-S	1M*36-S	2M*36-D	2M*36-D	24MB
111010	2M*36-D	4M*36-S			24MB
111011	2M*36-D	2M*36-D	2M*36-D	4M*36-S	40MB
111100	2M*36-D	2M*36-D	4M*36-S		32MB
111101	2M*36-D	2M*36-D	4M*36-S	4M*36-S	48MB
111110	2M*36-D	2M*36-D	8M*36-D		48MB
111111	2M*36-D	2M*36-D	8M*36-D	8M*36-D	80MB

Register 5A Hardware Default = 00

bit 7 Reserved and Should be Written with 0

bit 6 Overwrite the Cache Read Cycle Time 0 : Keep the access time that defined in the Register 50 bit 7. 1 : Force all the first cycle time of cache access to be 2T, it overwrites the bit 7 of register 50.

- bit 5 Reserved and Should be Written with 0
- bit 4 Reading the De-Turbo Status (Read Only) 0 : Turbo 1 : De-Turbo
- bit 3-2 Reserved and Should be Written with 0

bit 1 M7 CPU's L1 Cache Burst Write Timing Control

- 0 : Always support 3-2-2-2, regardless register 51 bit 1 and register 50 bit 7.
- 1 : Be able to support 2-1-1-1 This bit is vaild only when M7 CPU is used.





. . . .

bit 0	Local Master Acess DRAM Cycle CASh Delay 1T active 0 : Disable 1 : Enable
Register 5B	Hardware Default = 00
bit 7	SMM Enable

_ _ . . . _ _

0: Disabled

- - -

1 : Enabled

This bit is used to enable/disable the generation of SMI* or IRQ12/15 interrupt.

Stop Clock enable bit 6

0: Disabled

1: Enabled

This bit is used to enable/disable the generation of STPCLK* signal. When enabled, a sequence of reading I/O port 043h followed by reading I/O port 070h forces SiS85C471 to assert STPCLK*.

STPCLK* Auto Generation Select bit 5

0: Disabled

1: Enabled

When enabled, the SiS85C471 asserts STPCLK* when the system timer expires, the break switch is pressed or the software SMI port is accessed.

bit 4 System Management Mode Request Selection

0: By IRQ

1: By SMI

The SiS85C471 provides an alternative way to enter system management mode by using IRQn for those CPUs that do not have SMI* input pin. Note that , when bit 5 of Register 5B is set to 1, this bit should be set to 1. (For more details, please refer to Register 68,69)

bit 3 **IRQn Channel Selection** 0: SELECT IRQ12 1: SELECT IRQ15 This bit is valid only when Register 5B bit 4 is set to 0.



bit 2

SYSCLK Frequency Auto-Switch

0 : Disable

1 : Enable

During CPU clock scaling, SYSCLK will be changed to 7.159 MHz. Once CPU clock is resumed to the normal state, the SYSCLK will return to the frequency defined by register 60 bit 7-5 after 30ms. CPU clock scaling can be triggered by an active SMOUTn or STPCLK*.

bit 1 Relocate enable

1 : Disabled

0 : Enabled

If this bit is enabled and segments D and E are non-shadowed, and DRAM size is 1MB ,2MB, 4MB, 5MB, 6MB or 8MB, then 256KB DRAM relocation is enabled. Note that, when SMM RAM is used, this bit should be set to 1.

bit 0 Reserved

Register 5C Interrupt vector address trap mask 1

- bit 7 ~ 0
 bit [7:0] correspond to interrupt vector address of A[9:2]. If an interrupt event such as IRQn, INTn, or NMI occurs, CPU always accesses the corresponding interrupt vector from memory 0h to 03ffh. This register is used to mask out an interrupt vector while the SiS85C471 is monitoring interrupt events. (default should be set to INT8)
- **Register 5D** Interrupt vector address trap mask 2
 - bit 7 ~ 0 Correspond to address bit of A[9:2]
- Register 5E Interrupt vector address trap mask 3
 - bit 7 ~ 0 Correspond to address bit of A[9:2]

Register 5F

bit 7	Pin 41 Mutiplex Output Control	
	0: Pin 41 functions as SMOUT0	
	1: Pin 41 functions as FLASHWE*	

- bit 6 FLASHWE* Activity Control 0: FLASHWE* is driven low 1: FLASHWE* is driven high
- bit 5FLASHWE* Program Control0: FLASHWE* is always high1: FLASHWE* can be programmed by setting register 5F bit 6This bit also controls the function of register 75 bit 0, please refer toregister 75 bit 0.

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bit 4	Reload Events of System Event Timer Include Those Events Monitored by I/O Device Standby Timer 0 : Disable 1 : Enable
bit 3,2	System Eevent Timer and I/O Device Standby Timer Time Base Select 00 : 9.374 second 01 : 1.171 second 10 : 35.759 micro second 11 : 0.139 micro second
bit 1	Reserved and should be written to 0.
bit 0	Any Activity of Break Event Generate a SMI 0: Disable 1: Enable The break events are defined in register 63 bit 3-0. If this bit is enabled, any active break event will generate a SMI and set register 69 bit 3.
Register 60 (i	index 60) Hardware Default = 00
bit 7 ~ 5	Bus Clock Frequency Selection 000 : BUSCLK = 7.159 MHz 001 : BUSCLK = 1/10 XFCLK 010 : BUSCLK = 1/8 XFCLK 011 : BUSCLK = 1/6 XFCLK 100 : BUSCLK = 1/6 XFCLK 101 : BUSCLK = 1/4 XFCLK 110 : BUSCLK = 1/3 XFCLK 111 : BUSCLK = 1/2 XFCLK
bit 4	Zero Wait for 16-bit Memory or I/O Command 0: Disable 1: Enable
bit 3	16-bit I/O Read Cycle Command without Command Delay 0: Disable 1: Enable
bit 2	Decrease 16-bit I/O Read Cycle One AT Bus Clock

- 0: Disable
- 1: Enable
- bit 1~0 Reserved



Register 61 (index 61) Hardware Default = 09

bit 7, 6	16-Bit I/O Cycle Command Recovery Time Selection 00 : 8 BUSCLK 01 : 5 BUSCLK 10 : 3 BUSCLK 11 : 2 BUSCLK
bit 5, 4	8-Bit I/O Cycle Command Recovery Time Selection 00 : 16 BUSCLK 01 : 11 BUSCLK 10 : 7 BUSCLK 11 : 4 BUSCLK
bit 3	Reserved and should be written with 1
bit 2	16-bit Memory, I/O Wait State Selection 0 : 2 wait states 1 : 1 wait states
bit 1	8-bit Memory, I/O Wait State Selection 0 : 5 wait states 1 : 4 wait states
bit 0	Reserved and should be written with 1
Register 62	Reserved
Register 62 bit 7	Reserved Reserved
•	
bit 7	Reserved
bit 7 bit 6	Reserved Reserved and should be written with 1
bit 7 bit 6 bit 5-0	Reserved Reserved and should be written with 1

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bit 3	Stop Clock /Clock Scaling/Clock Throttling Break by IRQn 0 : Disabled 1 : Enabled This bit is used to allow IRQn to break system from idle mode when set.
bit 2	Stop Clock /Clock Scaling/Clock Throttling Break by NMI 0 : Disabled 1 : Enabled This bit is used to allow NMI to break system from idle mode when set.
bit 1	Stop Clock /Clock Scaling/Clock Throttling Break by DMA Request 0 : Disabled 1 : Enabled This bit is used to allow any DMA request to break system from idle mode.
bit 0	Stop Clock /Clock Scaling/Clock Throttling Break by Local Master request 0 : Disabled 1 : Enabled This bit is used to allow any local master request to break system from idle mode.
Register 64	Define Software_SMI low byte address A7 - A0
bit 7 ~ 0	This register defines the lower 8 bits of SW_SMI address trap address. bit[7:0] correspond to address A[7:0]. If SW_SMI is enabled (defined in register 68, bit 1), an I/O write to the address defined in Registers 64 and 65 will force the SiS85C471 to generate software SMI*. The software SMI* can be used to support APM.
Register 65	Define Software_SMI high byte address A15 - A8
Register 66	System event timer is reloaded by IRQ0~7 or Stop Clock Break selects Register 1.
bit 7	: IRQ7
bit 6	: IRQ6
bit 5	: IRQ5
bit 4	: IRQ4
bit 3	: IRQ3
bit 2	: IRQ2
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bit 1	: IRQ1
bit 0	: IRQ0
Register 67	System event timer is reloaded by IRQ8~15 or Stop Clock Break selects Register 2.
bit 7	: IRQ15
bit 6	: IRQ14
bit 5	: IRQ13
bit 4	: IRQ12
bit 3	: IRQ11
bit 2	: IRQ10
bit 1	: IRQ9
bit 0	 IRQ8 0 : IRQn active will force STPCLK* to go high, if the Register 63 bit 3 is enabled. 1 : IRQn active will not influence STPCLK*
Register 68	SMI/IRQ enable register
bit 7	I/O Device Standby timer time out control 0 : Disabled 1 : Enabled
bit 6	Programmable I/O Device Standby exit control 0 : Disabled 1 : Enabled
bit 5	Serial Port or Parallel Port Standby exit control 0 : Disabled 1 : Enabled
bit 4	Hard Disk standby exit control 0 : Disabled 1 : Enabled
bit 3	Screen save mode exit control 0 : Disabled 1 : Enabled

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bit 2	Break switch SMI/IRQ control 0 : Disabled 1 : Enabled
bit 1	Software SMI/IRQ control 0 : Disabled 1 : Enabled
bit 0	System event timer time out SMI/IRQ control 0 : Disabled 1 : Enabled
Register 69	SMI/IRQ request status register
bit 7	I/O device standby timer time out request
bit 6	Programmable I/O device standby exit request
bit 5	Serial port or parallel port standby exit request (refer to bit 0 and 1 of the Register 73 for the port selected)
bit 4	Hard disk standby exit request
bit 3	Local Standby / Clock Scaling / Clock Throttling exit request
bit 2	Break switch SMI/IRQ Request If the SMM was enabled and the Register 68 bit $2 = "1"$ and the Register 71 bit $7 = "0"$, then this bit can be set by writing an "1". If the Register 71 bit $7 = "1"$, this bit can be set by the RC or the De-Turbo pin.
bit 1	Sortware SMI/IRQ Request This bit can be set by enabling the Register 68 bit 1 and an I/O write to the address defined in the Registers 64 and 65.
bit 0	System event timer time out SMI/IRQ Request If the SMM is enabled and the register 5B bit 5 is set to 0 (disable) and the Register 68 bit 0 is set to 1 (enable), then this bit can be set to 1 when a time out of the system timer happens.
	Which of the SMI/IRQ functions should be serviced could be decided by the SMI handler while reading this register. 0: not requested 1: requested



Register 6A

bit 7 ~ 0 SMOUT 7 - 0

Register 6B SMI_CLR Register

When a SMI or IRQ12/15 is active, 85C471 will not allow a new SMI or IRQ12/15 generated until this register is wrote, CPU state have been restored, and a 6 us timer times out.

Register 6C SMI_MASK Register / Port 70h Shadow Register

Read from or write to this register has different meaning. When read this register, the index value written to port 70h is got. When a SMI or IRQ12/15 is active, 85C471 masks out CPU resets except those resets caused by shutdown cycle or hardware reset until this register is written, CPU state have been restored, and a 14 us timer times out.

Register 6D System Event Timer Low Byte

Register 6E System Event Timer High Byte

Each count represents 9.374 seconds. Maximum time count is 614325.08 seconds. If SMM and bit 0 of Register 68 are enabled, the system event timer starts counting down. When the timer counts down to 0, either SMI, IRQ12 or IRQ15 will be used as the system management request signal if bit 5 of Register 5B is disabled.

Time out period = (number of counts - 1) * Time Base

Register 6F System timer reload event detection

- bit 7 Local device detection control
 - 0: Disabled
 - 1: Enabled

bit 6 IRQn detection control

0 : Disabled 1 : Enabled If this bit is enabled, any IRQ that goes active except disabled by Registers 66 and 67 will reload system event timer.

bit 5 Video Acess Request (Memory Segment A0000h~BFFFFh, I/O Port 3B0h~3B7h, 3C0h~3CFh, 3D0h~3DFh)

- 0: Disabled
- 1 : Enabled


bit 4	0C0000-0C7FFF Address trap detection control 0 : Disabled 1 : Enabled
bit 3	INT vector address trap (0h - 03FFh) detection control 0 : Disabled 1 : Enabled
bit 2	DMA request detection control 0 : Disabled 1 : Enabled
bit 1	Local master request detection control 0 : Disabled 1 : Enabled
bit 0	Programmable I/O port detection control 0 : Disabled 1 : Enabled (Please refer to Registers 70 and 71)
Register 70	Programmable I/O port address register
bit 7 ~ 0	: A9 - A2
Register 71	
bit 7,6	Break switch pin select 0 X : Disabled 1 0 : the RC pin is used as the break switch pin
	1 1 : the De-Turbo pin is used as the break switch pin
bit 5	 1 1 : the De-Turbo pin is used as the break switch pin Pin 58 definition 0 : as SMOUT1 1 : as SMOUTW*
bit 5 bit 4,3,2	Pin 58 definition0 : as SMOUT11 : as SMOUTW*Programmable I/O port address mask000 : no mask001 : mask A0010 : mask A1-A0011 : mask A2-A0100 : mask A3-A0101 : mask A4-A0111 : mask A5-A0111 : mask A6-A0When Programmable I/O port detection control bit in the Register 6
	Pin 58 definition0 : as SMOUT11 : as SMOUTW*Programmable I/O port address mask000 : no mask001 : mask A0010 : mask A1-A0011 : mask A2-A0100 : mask A3-A0101 : mask A4-A0111 : mask A5-A0111 : mask A6-A0When Programmable I/O port detection control bit in the Register 6F bit0 is enabled, an I/O access to the address defined in the Registers 70

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bit 1,0 Programmable I/O port address A1, A0

When I/O trap address enable bit, bit 0 of Register 6F, is enabled, I/O command accessing the address defined by Registers 70 and 71 will force System Event Timer to be reloaded.

Register 72

bit 7 Clock throttling

0 : Disabled

1 : Enabled

When STPCLK* is active and this bit is enabled, a coming IRQ0 will force the STPCLK* to go inactive until an EOI command for the IRQ0 is issued.

bit 6 CPUCLK scaling controlled by SMOUT

0 : Disabled 1 : Enabled

bit 5 ~ 3 CPUCLK scaling control select

000 : by SMOUT0 001 : by SMOUT1 010 : by SMOUT2 011 : by SMOUT3 100 : by SMOUT3 100 : by SMOUT4 101 : by SMOUT5 110 : by SMOUT6 111 : by SMOUT7

bit 2,1 Definition for 116,133,134,137

- 0 0 : pin 116 = SMOUT2 pin 133 = ALT pin 134 = ALTWL* pin 137 = SMOUT3
- 0 1 : pin 116 = RAS4* pin 133 = ALT pin 134 = ALTWL* pin 137 = RAS5*
- 1 X : pin 116 = RAS4* pin 133 = RAS6* pin 134 = RAS7* pin 137 = RAS5*

If the external cache is set to write back mode (register 50 bit 3 = "1") then

1 0 : no Alter bit (always dirty)

1 1 : combine 7 tag bits + 1 Alter bit in one SRAM



Cuib	
bit 0	Port 92h support (functions defined by bit 1 and bit 0 only) 0 : Disabled 1 : Enabled
	This bit enables/disables the function of bit 0 and 1 of port 92h. The bit 1 of port 92h is ORed with Fast_A20_Gate internally to generate A20M*. If both this bit and Fast_A20_gate are 0, A20M* is at low state .
	Bit 0 of port 92h can be cleared by CPURESET or a I/O write operation. When register 50 bit 0 is set to 1, setting port 90 bit 0 to 1 from 0 by an I/O write to itself, an INIT is generated after a 2 us or 6 us delay depending on register 57 bit 3.
Register 73	I/O device standby monitor
bit 7	Programmable I/O ports defined by Registers 71 and 70 0 : Disabled 1 : Enabled
bit 6	I/O ports 1F0h to 1F7h and 3F6 detect - Hard Disk Port 0 : Disabled 1 : Enabled
bit 5	 I/O ports 2F8h to 2FFh, 3F8h to 3FFh, 2E8h to 2EFh, or 3E8h to 3EFh detect - Serial Port 0 : Disabled 1 : Enabled
bit 4	I/O ports 278h to 27Fh, 378h to 37Fh or 3BCh to 3BFh - Parallel Port 0 : Disabled 1 : Enabled
bit 3	IRQ1, 3, 4 and IRQ 12 detect - Screen save mode detect 0 : Disable 1 : Enable
bit 2	Screen save mode exit request status 0 : no any IRQ 1, 3, 4 or IRQ 12 request 1 : IRQ 1, 3, 4 or IRQ 12 request
bit 1	Serial Port standby exit control 0 : Disable 1 : Enable
bit 0	Parallel Port standby exit control 0 : Disable 1 : Enable
Register 74	I/O Device Standby Timer The time period of each count is according to the setting of register 5F bit 3,2. Maximum time period is 2399.75 seconds.The minimum count is 2.The timer expires when any of the selected event(s) in register 73

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bit 7-3 has been idle for a programmed period. Please refer to register 68 bit 7.

Time out period = (number of counts - 1) * Time Base

Register 75

bit 7	Reserved
bit 6	IORDY* Control 0: Disable 1: Enable During clock scaling, IORDY* for DMA or ISA Master transfer is active till memory transfer complete.
bit 5-4	Reserved
bit 3	A20ML Control 0 : Disable 1 : Enable When CPU executes SMI handler, A20ML goes high. After SMI handler is done, A20ML return to the previous state.
bit 2	RAS[7:4] Active Control 0 : Disable 1 : Enable
bit 1	MA bus and MWE buffers driving capacity control 0 : 12 mA 1 : 24 mA
bit 0	Flash Memory Write Control 0 : Enable 1 : Disable Once this bit is set to disable, it is not able to reprogrammable and any write to BIOS ROM area is void.
Register 76	
bit 7, 6, 5	Reserved and should be written with 0
bit 4	Stop Green Bus Cycle Detected 0 : Disable 1 : Enable This bit is valid only when Intel CPU or Am486plus is used. If this bit is enabled, STPCLK* can only be deasserted after Stop Grant Bus Cycle is detected.
bit 3,2,1	Reserved and should be written with 0
bit 0	Keyboard interface status (Read only) 0 : Keyboard interface is disabled 1 : Keyboard interface is enabled



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3.3 Application Description











4. PIN DESCRIPTION

4.1 Pin Assignment





1			
Pin listing (*	means active low)		
1 = 14MHZ	53 = SD15	105 = D/C*	157 = KA3X/KA3{IRQ4}
2 = BALE	54 = PD1	$106 = M/IO^*$	158 = KA3Y/KA2{IRQ1}
$3 = HDEN^*$	55 = SPK	107 = BLAST*	159 = MA10
$4 = LDEN^*$	56 = A20M*	108 = BE3*	160 = MA9
5 = BDIR	57 = A4	109 = BE2*	161 = MA8
6 = SDIR	58 = SMOUT1/SMOUTW*	110 = BE1*	162 = MA7
$7 = ASRTC^*$	59 = A5	111 = BE0*	162 = MA6
$8 = DRRTC^*$	60 = VSS	112 = BRDY*	164 = VSS
$9 = DWRTC^*$	61 = VDD	113 = PWRGD	165 = VDD
10 = VDD	62 = A6	114 = VDD	166 = MA5
10 = 700 11 = XD0	63 = A7	115 = CPURDY*	167 = MA4
12 = XD1	64 = A8	116 = RAS4*/SMOUT2	168 = MA3
12 = XD1 13 = XD2	65 = A9	117 = A3	169 = MA2
14 = XD3	66 = A10	118 = PCD	170 = MA1
15 = VSS	67 = A11	119 = VSS	170 = MA0
16 = XD4	68 = A12	120 = A2	172 = INTR
10 = XD4 17 = XD5	69 = A13	120 = A2 121 = LOCK*	172 = 1010 $173 = ZWS^*$
17 = XD3 18 = XD6	70 = A13	121 = LOCK 122 = LBD*	173 = 2W3 174 = IORDY
18 = XD0 19 = XD7	70 = A14 71 = A15	122 = LBD 123 = LRDY*	175 = MPXS2{IRQ11}
19 = XD7 20 = VSS	71 = A13 72 = A16	124 = TA7{IRQ15}	176 = MPXS1/RAS6*{IRQ10}
20 = V33 21 = PD0	72 = A10 73 = A17	$124 = TA7{IRQ13}$ 125 = TA6{IRQ14}	
	73 = A17 74 = A18		177 = MPXS0/RAS7*{IRQ9}
22 = PD2		$126 = TA5{IRQ12}$	$178 = MPXI2\{IRQ8\}$
23 = D16	75 = A19	$127 = TA4\{IRQ7\}$	$179 = MPXI1{IRQ6}$
24 = D17	76 = VSS	$128 = TA3\{IRQ3\}$	$180 = MPXI0{IRQ5}$
25 = VDD	77 = A20	$129 = TA2\{DRQ7\}$	181 = MEMCS16*
26 = D18	78 = A21	$130 = TA1\{DRQ6\}$	182 = VSS
27 = D19	79 = A22	$131 = TA0\{DRQ5\}$	$183 = IOCS16^*$
28 = D20	80 = A23	132 = TAWE*{WIRQ}	$184 = MASTER^*$
29 = D21	81 = A24	$133 = RAS6*/ALT{DTURBO}$	
30 = D22 31 = D23	82 = A25	$134 = RAS7*/ALTWE*{RC*}$	
	83 = A26	$135 = MWE^*$	187 = DACK5*(LGNT1*)
32 = HOLD	$84 = SMIACT^*$	136 = MRE*{IOCHK*} 137 = RAS5*/SMOUT3	188 = DACK3*(GN138)
$33 = BS16^*$	85 = KEN*		189 = DACK2*(C138) 190 = DACK1*(B138)
34 = D24	$86 = EADS^*$	138 = RAS3*/MA11	
35 = D25	87 = KBROMCS* 88 = A27	$139 = RAS2^*$	191 = DACK0*(A138)
36 = D26		$140 = RAS1^*$	192 = MEMR*
37 = D27	89 = A31	$141 = RAS0^*$	193 = MEMW*
38 = VSS	90 = HITM*	142 = VSS	194 = SMEMR*
39 = D28	91 = RSTCPU	143 = KREX*{RAS4*}	195 = SMEMW*
40 = D29	92 = VSS	144 = KREY*{RAS5*}	196 = SA1
41 = SMOUT0	93 = SMI*	145 = KWEX*{RAS6*}197	
42 = D30	94 = STPCLK*	146 = KWEY*{RAS7*}198	
43 = VDD	95 = HLDA	147 = VDD	199 = SYSCLK
44 = D31	96 = VSS	148 = KCE3*{DRQ0}	200 = VSS
45 = PD3	97 = VDD	149 = KCE2*{DRQ1}	201 = VDD
46 = SD8	98 = XFCLK	150 = KCE1*{DRQ2}	202 = AEN
47 = SD9	99 = IGNNE*	151 = KCE0*{DRQ3}	203 = BHE*
48 = SD10	100 = FERR*	$152 = CAS3^*$	204 = REF*
49 = SD11	101 = NMI	153 = CAS2*	205 = RSTDRV
50 = SD12	102 = INIT	154 = CAS1*	206 = TC
51 = SD13	103 = ADS*	155 = VSS	207 = IOR*
52 = SD14	104 = W/R*	$156 = CAS0^*$	208 = IOW*
NUTE: {???} fo	or non-cache mode, (??)	?) for VL-BUS master sup	port mode.

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4.2 Pin Definitions

4.2.1 CPU Interface

Pin No.	Symbol	Туре	Name and Function
103	ADS*	I/O (12) ¹	Address status is an input from CPU and local bus master, and an output to local bus targets in DMA/ISA master cycles. It is an active low signal that indicates a valid bus cycle definition and address are available on the cycle definition lines and address bus.
106	M/IO*	I/O (12) ¹	<i>Memory I/O</i> definition is an input from CPU and local bus master, and is an output to local bus targets in DMA/ISA master cycles. It indicates an I/O cycle when low, and a memory cycle when high.
104	W/R*	I/O (12) ¹	<i>Write/Read</i> definition is an input from CPU and local bus master, and is an output to local bus targets in DMA/ISA master cycles. It indicates a read cycle when low, and a write cycle when high.
105	D/C*	I	<i>Data/control</i> definition is an input to indicate a control cycle when low, and a data cycle when high.
115	CPURDY*	I/O (24) ¹	<i>CPU Ready</i> output indicates that the current cycle is complete when a VL-Bus master or the CPU accesses on-board memory or ISA target. It is connected to the ready-return of VESA slots. Once the SiS85C471 detects the active low of LBD*, CPURDY* becomes Hi-Z. The SiS85C471 will drive CPURDY* active if LRDY* is detected to be active low.
32	HOLD	O (6) ¹	The bus <i>hold</i> request is used to request the control of the CPU bus. HLDA will be asserted by the CPU after completing the current bus cycle.

Note 1: Driving Current. (Unit:mA)

Pin No.	Symbol	Туре	Name and Function
95	HLDA	I	Hold acknowledge comes from the CPU in response to a HOLD request. It is active high and remains driven during bus hold period. HLDA indicates that the CPU has given the bus to another bus master.
101	NMI	O (6) ¹	<i>Non-maskable inter</i> rupt is rising edge trigger signal to the CPU and is generated to invoke a non-maskable interrupt.
172	INTR	O (6) ¹	<i>Interrupt</i> goes high whenever a valid interrupt request is asserted. It is used to interrupt the CPU, and is usually connected to the CPU's interrupt pin.
33 56	BS16* A20M*	O (12) ¹ O (6) ¹	BS16* is a tri-state active low output used to indicate to the CPU or the VL-Bus master that the current target can only do 16-bit transfer. This signal is driven active by the SiS85C471 while the CPU or the VL-Bus master accesses the device which is not on-board memory. The BS16* will be in high impedance when LBD* is detected low. The BS16* will then be driven by the VL-Bus target if the target can not do 32-bit transfers. A20 Mask is the fast A20GATE output to the CPU. It remains high during power up and the CPU reset period. It will force A20 to go low when active.
86	EADS*	0 (12) ¹	<i>External address st</i> robe is a tri-state output pin. It indicates that a valid external address has been driven onto the 80486 CPU address pins. This address will be used for the CPU to perform an internal cache invalidation cycle. It is driven by the SiS85C471 during DMA or ISA master cycles. It is driven by the VL-Bus master during a VL-Bus master cycle.
100	FERR*	I	<i>Floating point error</i> from the 80486 CPU. It is driven active when a floating point error occurs.

*Note*¹: Driving Current. (Unit:mA)

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Pin No.	Symbol	Туре	Name and Function
99	IGNNE*	O(6) ¹	<i>Ignore numeric error</i> informs the 80486 CPU to ignore a numeric error.
107	BLAST*	I/O (6) ¹	The <i>burst last</i> signal indicates that the next time BRDY* is returned the burst bus cycle is complete. The signal is driven by the bus master or the CPU, and is sensed by bus targets. It is an input in a CPU or VL-Bus master cycle, and is an output in a DMA/ISA master cycle. Because the DMA/ISA master can not perform burst mode transfers, BLAST* is low always during these cycles.
112	BRDY*	I/O (12) ¹	<i>Burst Ready</i> indicates that data presented are valid during a burst cycle. It is driven by the SiS85C471 during non-local-bus cycles, and is driven by the VL-Bus target if LBD* is asserted low. BRDY* is an input when LBD* is detected active.
94	STPCLK*	0 (12) ¹	The SiS85C471 supports P24D/T, SL Enhanced 486 <i>stop clock</i> function by asserting STPCLK* in power saving mode. For Cyrix CPUs, it is connected to the SUSP# pin.

*Note*¹: Driving Current. (Unit:mA)



4.2.2 Local Bus and Bus Control

Pin No.	Symbol	Туре	Name and Function
121	LOCK*	I	<i>The bus lock</i> pin indicates that the current bus cycle is locked. The CPU will not allow a bus hold when LOCK* is asserted.
122	LBD*	I	<i>Local bus</i> device cycle input to indicate a local bus device cycle.
123	LRDY*	I	Local bus device ready is an active low input to indicate that the current local bus cycle is complete. The SiS85C471 either synchro- nizes it or passes it through to generate the CPURDY*.
111-108	BE0 - 3*	I/O (6) ¹	Byte enables determine the bytes to be accessed during CPU or DMA/ISA master cycles. During CPU cycles, they are encoded to generate SA1, SA0, and BHE*. During DMA or ISA master cycles, SA1, SA0 and BHE* are used to generate the byte enable signals.
120,117,57 ,59, 62-75,77- 83,88,89	A2,A3, A4-A15 A16-A27,A31	I/O (6) ¹	<i>CPU address lines</i> . They are outputs during DMA or ISA master cycles.
197	SA0	I/O (12) ¹	AT bus address 0. It is an output during the AT or DMA cycles, and an input during the ISA master cycles. It is LOW during 16-bit access cycles.
196	SA1	I/O (12) ¹	<i>AT bus address 1</i> . It is an output during the AT or DMA cycles, and an input during the ISA master cycles.
203	BHE*	I/O (12) ¹	<i>Byte high enable signal</i> indicates that the high byte has valid data on the ISA 16-bit data bus. This signal is an output except in ISA master mode.
192	MEMR*	I/O (12) ¹	AT-bus memory read command signal is an output pin during AT/DMA/refresh cycles and is an input pin in ISA master cycles. It is used to retrieve data from the ISA bus memory.

*Note*¹: Driving Current. (Unit:mA)

Pin No.	Symbol	Туре	Name and Function
193	MEMW*	I/O (12) ¹	AT-bus memory write command signal is an output pin during AT/DMA cycles and is an input pin in ISA master cycles. This active low signal writes data into the ISA bus memory.
194	SMEMR*	O (12) ¹	<i>AT-bus memory read.</i> It instructs the memory devices to drive data onto the data bus. It is active only when the memory to be accessed is within the lowest 1MB.
195	SMEMW*	O (12) ¹	AT-bus memory write. It instructs the memory devices to store the data present on the data bus. It is active only when the memory to be accessed is within the lowest 1MB.
207	IOR*	I/O (24) ¹	AT-bus I/O read command signal is an output pin during AT or DMA cycles and is an input pin in ISA master cycles. When low, it strobes an I/O device to place data on the data bus.
208	IOW*	I/O (24) ¹	AT-bus I/O write command signal is an output pin during AT or DMA cycles and is an input pin in ISA master cycles. When low, it strobes data on the data bus into a selected I/O
2	BALE	0 (12) ¹	device. Bus address latch enable is used on the ISA bus to latch valid address from the CPU. Its falling edge starts the ISA command cycle.
181	MEMCS16*	I	16-bit memory chip select indicates a 16-bit memory transfer when asserted or an 8-bit memory transfer when it is negated.
183	IOCS16*	I	<i>16-bit I/O chip select</i> indicates that the AT bus cycle is a 16-bit I/O transfer when asserted or an 8-bit I/O transfer when it is negated.
173	ZWS*	I	Zero wait state is an active low signal. The system ignores the IORDY signal and terminates the AT bus cycle without additional wait state when it is asserted.

Note 1: Driving Current. (Unit:mA)

Chip

Pin No.	Symbol	Туре	Name and Function
174	IORDY	I/O (24) ¹	I/O channel ready is normally high. It can be pulled low by the slow devices on the AT bus to add wait states for the ISA memory or I/C cycles. When a DMA or an ISA master accesses a VL-Bus target, IORDY is an output to control the wait states.
184	MASTER*	I	<i>Master*</i> is an active low signal from AT bus When active, it indicates that the ISA bus master takes over the control of the system The address and control signals are all driver by the ISA bus master.
202	AEN	O (12) ¹	Address Enable is driven high on the ISA bus to indicate the address lines are valid in DMA or ISA master cycles. It is low otherwise.
3	HDEN*	O (6) ¹	<i>High Byte data enable</i> signal enables the high byte buffer of the SD bus.
4	LDEN*	O (6) ¹	<i>Low Byte data enable</i> signal enables the buffer of the XD bus.
5	BDIR	O (6) ¹	Data Buffer Direction controls the direction of the buffers between SD15-SD8 and D15-D8 and the direction of the buffers between the XD bus and D7-D0. A HIGH sets the data path from D15-D8 (D7-D0) to the SD (XD) bus and a LOW sets the data path from the SD (XD) bus to D15-D8 (D7-D0).
6	SDIR	O (6) ¹	SD low byte Data Direction controls the direction of the low byte buffers between SD and XD. A HIGH sets the data path from XD to SD and a LOW sets the data path from SD to XD.
7	ASRTC	O (6) ¹	Address strobe of the real time clock device is used to latch the address from XD bus when the CPU accesses the RTC.
8	DRRTC*	O (6) ¹	Data read strobe of the real time clock device is used to drive data onto the XD bus when the CPU accesses the RTC.

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Pin No.	Symbol	Туре	Name and Function
9	DWRTC*	O (6) ¹	Data write strobe of the real time clock device is used to store the data presented on the XD bus when the CPU accesses the RTC. This pin must be connected to the R/W of the RTC.
206	тс	O (12) ¹	Terminal count gives information concerning the completion of DMA transfers. A pulse is generated by the DMA controller when the terminal count (TC) of any channel reaches except for channel 0 in memory-to- memory mode. During memory-to-memory transfers, TC will be asserted when the TC for channel 1 occurs. When a TC pulse occurs, the DMA controller will terminate the service, and if auto-initialize is enabled, the base registers will be written to the current registers of that channel. The mask bit and the TC bit in the Status word will be set for the currently active channel unless the channel is programmed for auto-initialize. In that case, the mask bit remains clear.
11-14, 16-19	XD0-7 /SMOUT0-7	I/O (12) ¹	Peripheral data bus lines. They are the system Management Output Port when in system management mode.
46-53	SD8-15	I/O	Data bus high byte for the ISA bus.
23,24, 26-31	D16-23	(12) ¹ I/O (12) ¹	Data bus bits 16-31 for the microprocessor, the memory, and the I/O devices.
34-37 39,40,42,44	D24-27 D28-31		

*Note*¹: Driving Current. (Unit:mA)



4.2.3 CLK and Reset

Pin No.	Symbol	Туре	Name and Function
98	XFCLK	I	<i>Clock input</i> of the SiS85C471. This input supplies the clock for the state machines of the memory/cache controller and the CPU/VL-Bus interface control. It should be the same frequency as the CPU and VL-Bus master. It should lead the CPU clock by 3-5ns.
199	SYSCLK	O (12) ¹	<i>ISA bus clock</i> , for ISA bus controller, ISA bus interfaces and the DMA controller. It can be programmed to derive from the XFCLK or from the 14MHz clock.
1	14MHZ	I	<i>14MHz</i> is an clock input for the timer and the DMA controller. It is 14.318MHz and is generated by an external oscillator.
113	PWRGD	I	<i>Power good</i> is a power on reset and push button reset input. It is high when in normal operation. The low to high transition is used by the SiS85C471 to latch the hardware trapping pins.
91	RSTCPU	O (12) ¹	<i>Reset CPU</i> is an active high output to reset the CPU.
205	RSTDRV	O (12) ¹	<i>Reset driver</i> is an active high output for a system reset.
102	INIT (WM_RST)	O (6) ¹	The <i>INIT</i> ialization output pin forces the P24D /T to begin execution in a know state. The P24D/T state after INIT is the same as the state after RESET except that the internal caches, floating point registers and the SMM base register retain whatever values they had prior to INIT.

Note 1: Driving Current. (Unit:mA)



4.2.4 Cache and DRAM Interfaces

Pin No.	Symbol	Туре	Name and Function
85	KEN*	O (6) ¹	The 80486 CPU <i>cache enable</i> pin is used when the current cycle is cacheable to the internal cache of the CPU. It is an active low signal asserted by the SiS85C471 during cacheable cycles.
118	PCD	I	Page cache disable pin reflects the state of the page attribute bits of the 80486 CPU.
			When using P24D or P24T CPU, this pin is defined as CACHE*.
204	REF*	I/O (24) ¹	<i>Refresh</i> signal is used to initiate a refresh cycle. This signal is an input in ISA bus master cycles and is an output in other cycles.
135	MWE*	O (12/ 24) ¹	<i>Memory write enable</i> is an active low output signal to enable local DRAM writes.
136	MRE*{IOCHK *}	I/O (12) ¹	<i>Memory read enable</i> is an active low output signal to enable local DRAM reads. In a non-cache system, it is defined as IOCHK*.
124-128	TA7,6{IRQ15 ,14} TA5{IRQ12} TA4{IRQ7} TA3{IRQ3}	I/O (6) ¹	<i>Tag RAM data bus lines.</i> In a cached system, they are defined as the tag data lines to the tag RAM. In a non-cached system, they are defined as the Interrupt request lines. The interrupt request lines can be edge triggered or level triggered. For edge triggered interrupts, they are detected at the low-to-high rising edge; for level triggered interrupts, the high level inputs trigger the interrupt. The interrupt inputs must keep in high level until they are acknowledged.
129-131	TA2-0{DRQ7-5}	I/O (6) ¹	In a cached system, they are defined as the Tag RAM Data Bus Lines 2 to 0. In a non-cached system, they are defined as the DMA request lines 7 to 5.
132	TAWE*{WIRQ}	O (6) ¹	<i>Tag RAM</i> write enable is an active low signal in a cached system. In a non-cached system, it is the interrupt request line for co-processor.

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Pin No	Symbol	Type	Name and Function
145	Symbol KWEX*{RAS6*}	Type O	Cache write enable for even bank. In a non-
143	KWEX (KASO)	(12) ¹	cached system, this pin is defined as DRAM Row Address Strobe 6.
146	KWEY*{RAS7*}	0	Cache write enable for odd bank. In a non-
		(12) ¹	cached system, this pin is defined as DRAM Row Address Strobe 7.
143	KREX*{RAS4*}	0	Cache read enable for even bank. In a non-
		(12) ¹	cached system, this pin is defined as DRAM Row Address Strobe 4.
144	KREY*{RAS5*}	0	Cache read enable for odd bank. In a non-
		(12) ¹	cached system, this pin is defined as DRAM Row Address Strobe 5.
151-148	KCE0*-3*	I/O	Cache byte enables are active low signals.
	{DRQ3- DRQ0}	(12) ¹	They are asserted to access the correspond- ing bytes in the second level cache. In a non- cached system, they are the DMA Requests.
133	RAS6*/ALT	I/O	Alter bit of cache indicates that the cache data
	{DTURBO}	(6)1	line has been modified. In a non-cached system, it is used as the DE-TURBO pin.
			DRAM Row Address Strobe 6 is active low.
			(Please refer to Register 72 for details)
134	RAS7*/ALTW E* {RC*}	I/O (6) ¹	Alter bit write enable is the write strobe to the alter RAM. This signal is active low to update the ALT bit when cache read miss or cache write hit occurs. In a non-cached system, it is an active low reset input from Keyboard controller to reset the CPU.
			DRAM <i>Row Address Strobe</i> 7 is active low.
			(Please refer to Register 72 for details)
158	KA3Y/KA2{IR Q1}	I/O (12) ¹	KA3Y-Cache address 3 for odd bank when Cache interleave mode is used. KA2-Cache address 2 when Cache non-interleave mode is used. IRQ1- Interrupt request level 1 when non-Cached mode is used.
157	KA3X/KA3{IR Q4}	I/O (12) ¹	KA3X-Cache address 3 for even bank when Cache interleave mode is used. KA3-Cache address 3 when Cache non-interleave mode is used. IRQ4-Interrupt request level 4 when non-Cached mode is used.

S	
Chip)

Pin No.	Symbol	Туре	Name and Function			
21,54 22,45	PD0-3	I/O (12) ¹	<i>DRAM parity bits</i> generate even parity bits in memory write cycles and accept even parity bits in memory read cycles.			
93	SMI*	O (12) ¹	System Management Interrupt. This pin is th SMI* output pin to the CPU SMI* input. It i used to generate the System Managemen Interrupt to the CPU for power saving.			
84	SMIACT*	I	The SMIACT* pin is used as the SMI acknowledgement input from the CPU to indicate that the SMI is being acknowledged. It is connected to the SMIACT*/SMADS* output of the CPU.			
90	HITM*	I	The <i>HIT Modified</i> line input pin is active LOW when an inquire cycle hits a modified line in the CPU. It is used to inhibit another bus master from accessing the data line until the line is completely written back.			
139-141	RAS2-0*	O (12) ¹	DRAM <i>Row Address Strobes</i> 0, 1 and 2. They are active low to latch the row address to DRAMs.			
152-154, 156	CAS3-0*	O (24) ¹	DRAM <i>Column Address Strobes</i> . They are the DRAM data output enable signals for bytes 3, 2, 1 and 0 respectively.			
138	RAS3*/MA11	O (12) ¹	It can be configured as Row Address Strobe 3 or Memory Address bit 11. When 16M DRAM SIMMs are used, it is configured as MA11. In that way, DRAM bank 3 is not supported. When configured as RAS3*, four banks of DRAMs are supported.			
159-163, 166-171	MA10-6 MA5-0	0 (12/ 24) ¹	DRAM multiplexed address lines 10 to 0.			

Note 1: Driving Current. (Unit:mA)



4.2.5 Multiplexer and Others

Pin No.	Symbol	Туре	Name and Function
177 176 175	MPXS0/RAS7* {IRQ9} MPXS1/RAS6* {IRQ10} MPXS2{IRQ11}	I/O (6) ¹	<i>Multiplexers I/O</i> selection pins. In a non- cached system, they are "Interrupt Request" (input) pins. Pins 176 and 177 can be configured as the RAS6* and the RAS7* if a "0" is identified on the SMOUT0 signal during power-up stage. (See Section 3.1 for details)
180 179 178	MPXI0{IRQ5} MPXI1{IRQ6} MPXI2{IRQ8}	I	<i>Multiplexers I/O</i> input pins. In a non-cached system, they are "Interrupt Request" pins.
191-185	DACK0*(A138) DACK1*(B138) DACK2*(C138) DACK3*(GN13 8) DACK5*(LGN T1*) DACK6*(LRE Q1*) DACK6*(LRE Q2*)	I/O(6) ¹ I/O(6) ¹ I/O(6) ¹ I/O(6) ¹ I/O(6) ¹ I/O(6) ¹	When pin 55(SPK) is pulled down, the pins 191~185 are the DMA acknowledges DACK0* ~3* and DACK5*~7*. Each is used to indicate that the DMA device has been granted the DMA access cycles. The active polarity of these lines is programmable. Reset initializes them to be active low. Because these signals are used internally for cascading the DMA channels and for DMA page register selection, these signals must be programmed to be active low. If pin 55(SPK) is pulled up, the pins 191~188 are the control signals of 74LS138. They are decoded by LS138 to generate the DMA acknowledge signals. Please refer to block diagram for details. Pins 187~185 are used as the arbitration signals for VL-Bus master arbitration. Pins 191~188 are also used as hardware trapping purpose to identify the hardware configuration during power up. Please refer to System Hardware Configuration for details.
87	KBROMCS*	O(6) ¹	Keyboard controller 8042 or system ROM chip select output.
55	SPK	I/O(6) ¹	<i>Speaker</i> is the output for speaker. When PWRGD is low, SPK is used as an input for hardware trap purpose.

Note 1: Driving Current. (Unit:mA)

Pin No.	Symbol	Туре	Name and Function
41	SMOUTO	O (6) ¹	The System Management Ourput 0 is an active low signal. When system timer expires, the break switch is pressed or the SMI port is accessed, the SMOUT0 will output what is programmed in bit 0 of the Register 6A. The STPCLK* will also go active low. If the I/O timer time out occurs, the SMOUT0 will output what is programmed in bit 4 of the Register 6A. SMOUT0 is also used as a hardware trap pin. (Please refer to Section 3.1 for details)
58	SMOUT1/ SMOUTW*	O (6) ¹	The System Management Ourput 1 is an active low signal. When system timer expires, the break switch is pressed or the SMI port is accessed, the SMOUT1 will output what is programmed in bit 1 of the Register 6A. The STPCLK* will also go active low. If the I/O timer time out occurs, the SMOUT0 will output what is programmed in bit 5 of the Register 6A.
			The System Management Output Port Write Latch pin indicates that the SMOUT7 ~ 0 can be latched from the XD bus through this pin.
			After I/O writes to port 22h with index 6A, then I/O writes to port 23h which can make SMOUTW* active.
116	RAS4*/SMOUT2	O (12) ¹	The System Management Ourput 2 is an active low signal. The function of the SMOUT2 is the same as the SMOUT1 except that it outputs what is in bit 2 (bit 6) of the Register 6A.
			DRAM <i>Row Address Strobe 4</i> is an active low signal. (See the Register 72 for Details)
137	RAS5*/SMOUT3	0 (12) ¹	The System Management Ourput 3 is an active low signal. The function of the SMOUT3 is the same as the SMOUT1 except that it outputs what is in bit 3 (bit 7) of the Register 6A
	ng Current (Lloitur A		DRAM <i>Row Address Strobe 5</i> is an active low signal. (See the Register 72 for Details)

*Note*¹: Driving Current. (Unit:mA)

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Pin No.	Symbol	Туре	Name and Function
10,25,	VCC		+5V DC Power
43,61,			
97,114,1			
47,			
165,			
201			
15,20,	GND		Ground
38,60			
76,92,			
96, 119,			
142,			
155,164,			
182,			
198,200			



5. ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Parameter	Min	Max	Unit
Ambient operating temperature	0	70	oC
Storage temperature	-40	125	oC
Input voltage	-0.3	5.5	V
Output voltage	-0.5	5.5	V

Note:

Stress above these listed may cause permanent damage to device. Functional operation of this device should be restricted to the conditions described under operating conditions.

5.1 DC Characteristics

 $T_{\mbox{\scriptsize A}}$ = 0 - 70 $^{0}\mbox{\scriptsize C},$ $\mbox{\scriptsize V}_{\mbox{\scriptsize DD}}$ = 5 V \pm 5 % , GND = 0 V

Symbol	Parameter	Min	Max	Unit	Condition
VII	Input low voltage	-0.5	0.8	V	
VIH		2.0	VDD+0.5	V	
VOI	Output low voltage	-	0.45	V	I _{OI} = 4.0 mA
VOH	Output high voltage	2.4	-	V	I _{OH} = - 1.0 mA
III	Input leakage current	-	<u>+</u> 10	uA	0 < V _{IN} < V _{DD}
I _{OZ}	Tristate leakage current	-	<u>+</u> 20	uA	0.45 < V _{OUT} < V _{dd}



5.2 AC Characteristics for 33/50 MHz

T_{A} = 0 - 70 $^{0}C,\,V_{DD}$ = 5 V \pm 5 % , Vss = 0 V, CL = 85/50* pf

Symbol	Parameter	Min	Тур	Max	Unit
T1	KCE* active delay (Note 3)	4	12	18	ns
T2	KCE* inactive delay	4	12	17	ns
Т3	Tag address input setup time	6			ns
T4	BRDY* active delay	7	11	17	ns
T5	BRDY* inactive delay (Note 1)	7	12	17	ns
T6	BLAST* setup time	2			ns
T7	KEN* active delay*	8	16	25	ns
T8	Cache Interleave KRE* active delay	5	9	13	ns
Т9	Cache Interleave KRE* inactive delay	4	8	12	ns
T10	KA3X valid delay (Note 2)	4	8	13	ns
T11	KA3Y/KA2 valid delay (Note 2)	5	10	14	ns
T12	Cache Non-interleave KRE* active delay	5	11	16	ns
T13	Cache Non-interleave KRE* inactive delay		14	20	ns
T14	ADS*, W/R* setup time	1			ns
T15	KWE* active delay	4	10	16	ns
T16	KWE* inactive delay	4	10	16	ns
T17	CPURDY* active delay	7	12	20	ns
T18	CPURDY* inactive delay (Note 1)	7	13	20	ns
T19	Tag address output valid delay	10	25	40	ns
T20	Tag address output floating delay	10	24	40	ns
T21	TAWE* active delay	6	14	23	ns
T22	TAWE* inactive delay	6	16	23	ns
T23	ALTWE* active delay*	5	13	22	ns
T24	ALTWE* inactive delay*	5	15	23	ns
T25	MRE* active delay	9	14	22	ns
T26	MRE* inactive delay	6	13	20	ns
T27	RAS* active delay	7	12	20	ns
T28	CAS* active delay	7	17	25	ns
T29	CAS* inactive delay	6	12	19	ns
T30	Column address valid delay	7	15	25	ns
T31	MWE* active delay	6	13	20	ns
T32	MWE* inactive delay	6	12	19	ns

(To be continued)

Notes :

1. The Min value assume $T_A=~70~^oC,\,V_{DD}=4.75$ V ,and CL = 85 pf .

- 2. Specications assume CL = 50 pf.
- 3. The cache SRAM with 20ns access speed should be used for both 33MHz and 50 MHz.



Chip AC Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
T38	RAS* inactive delay	6	12	19	ns
T39	Row Address valid delay	9	17	25	ns
T40	Fast cache write RDY* active delay	7	12	16	ns
T41	ALE active delay from SYSCLK falling	8	16	28	ns
T42	ALE inactive delay from SYSCLK	10	23	45	ns
T43	MEMCS16* set up time to SYSCLK	0			
T44	MEMCS16* hold time to SYSCLK	7			ns
T45	IOCS16* set up time to SYSCLK	4			ns
T46	IOCS16* hold time to SYSCLK	3			ns
T47	Command active delay from SYSCLK	8	20	42	ns
T48	Command inactive delay from SYSCLK	7	15	27	ns
T49	ZWS* set up time to SYSCLK	4			ns
T50	ZWS* hold time from SYSCLK	5			ns
T51	HDEN* active delay from BS16*	6	18	27	ns
T52	HDEN* inactive delay from BS16*	8	15	33	ns
T53	SDIR, BDIR active delay from BS16*	10	22	35	ns
T54	SDIR, BDIR inactive delay from BS16*	7	20	30	ns
T55	Data conversion SA0 delay from SYSCLK	6	21	30	ns
T56	Data conversion SA0 delay from SYSCLK	10	23	43	ns
T57	Address bus valid delay from REF*	9	25	50	ns
T58	Address bus float delay from REF*	7	23	44	ns
T59	Address set up time to IOR*, IOW* active	16			ns
T60	Address hold time from IOR*, IOW* inactive	0			ns
T61	SDIR, BDIR delay from command active	8	18	33	ns
T62	SDIR, BDIR delay from command inactive	20	45	84	ns
T63	SDEN*, HDEN* delay from command active	10	25	45	ns
T64	SDEN*, HDEN* delay from command inactive	20	35	55	ns
T65	Data valid delay form BS16*	3	23	40	ns
T66	Data valid delay from SYSCLK	19	45	68	ns
T67	Data floating delay from BS16*	8	20	35	ns
T68	D15-0 data set up time to command inactive	15			ns
T69	D15-0 data hold time to command inactive	8			ns
T70	D7-0 data valid delay from SYSCLK	12	30	60	ns
T71	D15-8 data valid delay from SYSCLK	12	30	60	ns
T72	D23-16 data valid dealy from SYSCLK	15	38	90	ns
T73	D31-24 data valid delay from SYSCLK	16	40	90	ns
T74	D15-0 data valid delay from D31-16 valid	12	20	40	ns
T75	D7-0 data valid delay from D31-24 valid	15	35	65	ns
T76	D7-0 data valid delay from D23-16 valid	12	21	40	ns
T77	D7-0 data valid delay from D15-8 valid	13	40	60	ns

(To be continued)



AC Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
T78	Data valid delay from command active	16	29	54	ns
T79	Data float dealy from command inactive	15	35	65	ns
T80	DMA clock delay form bus clock			8	ns
T81	Low byte address valid delay			50	ns
T82	Low byte address invalid delay			45	ns
T83	Page address valid delay			60	ns
T84	Page address invalid delay			47	ns
T85	DACKn* active delay			41	ns
T86	DACKn* inactive delay			50	ns
T87	IOR* or MEMR* active delay			55	ns
T88	IOR* or MEMR* inactive delay			40	ns
T89	IOR* or MEMR* hold time	0			ns
T90	IOW* or MEMW* active delay			50	ns
T91	IOW* or MEMW* inactive delay			35	ns
T92	TC active delay			40	ns
T93	TC inactive delay			60	ns
T94	RSTDRV active delay	8	13	20	ns
T95	RSTDRV inactive delay	9	22	40	ns
T96	RSTCPU active delay*	6	9	18	ns
T97	RSTCPU inactive delay*	7	15	25	ns
T98	RSTCPU duration	25			XFCLK
T101	LBD* latch setup time	1			ns
T102	LBD* latch hold time	6			ns
T103	CPURDY*, BS16*, BRDY* floating delay from	7	15	25	ns
	LBD* active low				
T104	LRDY*, BRDY*, CPURDY* setup time,	1			ns
	detected by SiS85C471				
T105	LRDY*, BRDY*, CPURDY* hold time,	6			ns
	detected by SiS85C471				
T106	CPURDY* floating delay from LRDY* falling	4	9	14	ns
	(Transparent mode)				
T107	CPURDY* rising delay from LRDY* rising	4	10	16	ns
	(Transparent mode)	_			
T111	ISA command setup time, detected by	3			
T 1 1 0	SiS85C471	_	1.0	4.0	
T112	ADS*,EADS* active delay	7	12	16	ns
T113	ADS* ,EADS* inactive delay (Note 1)	9	13	20	ns
T114	W/R*, M/IO* active delay from ISA command	9	18	19	ns
T 445	active low	-	4.0		
T115	W/R*, M/IO* inactive delay from ISA	1	16	20	ns
	command inactive				

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(To be continued)

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AC Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
T116	IORDY active low delay from LBD* active low	6	16	30	ns
T117	IORDY inactive delay from XFCLK(*1)	7	15	23	ns
T118	VL-Bus data setup time	2			ns
T119	VL-Bus data hold time	7			ns
T120	ISA-Bus data valid delay from VL-Bus data valid (read from VL-Bus)	14	32	54	ns
T121	ISA-Bus data floating delay from ISA command inactive (read from VL-Bus)	10	20	35	ns
T122	VL-Bus data valid delay from LBD* active low (write to VL-Bus)	9	15	30	ns
T123	VL-Bus data floating delay from ISA command inactive (write to VL-Bus)	8	20	35	ns
T124	VL-Bus master LREQ* input setup time	2			ns
T125	VL-Bus master LREQ* inactive setup time	2			ns
T126	VL-Bus master LGNT* active delay time	8	20	35	ns
T127	VL-Bus master LGNT* inactive delay time	6	16	25	ns
T128	Burst mode access DRAM BRDY* active delay time	6	12	16	ns
T129	LGNT* inactive to LREQ* inactive delay time			5	us
T130	SMI*,STPCLK*,INIT, active delay time	3	9	15	ns
T131	SMI* floating delay	8	15	25	ns
T132	IORDY active low delay from HITM* active low			36	ns

(End)

1: At the T-state which CPURDY, LRDY*, or BRDY* is detected active by SiS85C471.



5.3 Timing Diagram







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CACHE READ HIT (CACHE NON-INTERLEAVE) BURST CYCLE



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CACHE READ MISS (UPDATE CACHE) CACHE NON-INTERLEAVE 3-2-2-2 XFCLK ADS* KCE [0:3]* ____T20 T19 TA [16:23] OUT IN IN IN KWEX* ▶ ∖ T15 T16 T22 TAWE* T21 • • T24 ALTWE* T23 Г18 CPURDY* T25 MRE* -> CACHE WRITE HIT BURST CYCLE CACHE INTERLEAVE, PAGE START 5-4-4-4 (EXTERNAL CACHE AT WRITE THROUGH MODE) XFCLK ADS* T4 BRDY* RDY* T27 RASn* T29 T28 CASn* T16 T15 KWEX* T16 T15 KWEY* T10 KA3X T11 KA3/KA2 Preliminary V6.0 August 19, 1994 67 Silicon Integrated Systems Corporation



2-1-1-1 (EXTERNAL CACHE AT WRITE BACK MODE) XFCLK ADS* T16 T15 4 KWEX* T16 T15 KWEY* BRDY* T10 Г11 KA3X KA3/KA2 WRITE HIT BURST CYCLE, CACHE INTERLEAVE (EXTERNAL CACHE AT WRITE BACK MODE) 3-2-2-2 XFCLK ADS* Τ5 тΛ BRDY* T17 RDY* T16 T15 KWEX* T16 T15 KWEY* T10 KA3X KA3/KA2 Preliminary V6.0 August 19, 1994 68 Silicon Integrated Systems Corporation

WRITE HIT CYCLE, CACHE INTERLEAVE





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AT WRITE CYCLE (16-bit)









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SNOOP CYCLE BY VESA MASTER



SNOOP CYCLE BY DMA OR ISA MASTER



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5.4 MECHANICAL DIMENSION (FOR SiS85C471)

QFP208-P

(208-Pin Plastic Flat Package)

Unit: mm





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